

2M x 4BANKS x 32BITS SDRAM*Table of Content-*

1.	GENERAL DESCRIPTION.....	3
2.	FEATURES.....	3
3.	PART NUMBER INFORMATION.....	3
4.	BALL CONFIGURATION.....	4
5.	BALL DESCRIPTION.....	5
6.	BLOCK DIAGRAM.....	6
7.	FUNCTIONAL DESCRIPTION.....	7
7.1	Power Up and Initialization.....	7
7.2	Programming Mode Register.....	7
7.3	Bank Activate Command.....	7
7.4	Read and Write Access Modes.....	7
7.5	Burst Read Command.....	8
7.6	Burst Write Command.....	8
7.7	Read Interrupted by a Read.....	8
7.8	Read Interrupted by a Write.....	8
7.9	Write Interrupted by a Write.....	8
7.10	Write Interrupted by a Read.....	8
7.11	Burst Stop Command.....	9
7.12	Addressing Sequence of Burst Type.....	9
7.13	Auto-Precharge Command.....	10
7.14	Precharge Command.....	10
7.15	Self Refresh Command.....	10
7.16	Power Down Mode.....	11
7.17	No Operation Command.....	11
7.18	Deselect Command.....	11
7.19	Clock Suspend Mode.....	11
8.	TABLE OF OPERATING MODES.....	12
7.13	8.1 Simplified State Diagram.....	13
9.	ABSOLUTE MAXIMUM RATINGS.....	14
10.	RECOMMENDED DC OPERATING CONDITIONS.....	14
11.	CAPACITANCE.....	14
12.	DC CHARACTERISTICS.....	15

13. AC CHARACTERISTICS.....	16
14. TIMING WAVEFORMS.....	18
14.1 Command Input Timing.....	18
14.2 Read Timing.....	19
14.3 Control Timing of Input/Output Data.....	20
14.4 Mode Register Set Cycle.....	22
14.5 Interleaved Bank Read.....	23
14.6 Interleaved Bank Read.....	24
14.7 Interleaved Bank Read.....	25
14.8 Interleaved Bank Read.....	25
14.9 Interleaved Bank Write.....	27
14.10 Interleaved Bank Write.....	27
14.11 Interleaved Bank Write.....	28
14.12 Page Mode Read.....	29
14.13 Page Mode Read/Write.....	30
14.14 AutoPrecharge Read.....	31
14.15 AutoPrecharge Write.....	32
14.16 AutoRefresh Cycle.....	33
14.17 SelfRefresh Cycle.....	34
14.18 Bust Read and Single Write.....	35
14.19 PowerDown Mode.....	36
14.20 AutoPrecharge Timing.....	37
14.21 AutoPrecharge Timing.....	38
14.22 Timing Chart of Write-to-Read Cycle.....	39
14.23 Timing Chart of Burst Stop Cycle.....	39
14.24 Timing Chart of Burst Stop Cycle (Precharge Command).....	40
14.25 CKE/DQM Input Timing.....	41
14.26 CKE/DQM Input Timing.....	42
14.27 Self Refresh/Power Down Mode Exit Timing.....	1
15. PACKAGE DIMENSIONS.....	44
15.1 VFBGA 90 balls pitch=0.8mm.....	44
16. REVISION HISTORY.....	45

1. GENERAL DESCRIPTION

PT480832BG is a high-speed synchronous dynamic random access memory (SDRAM), organized as 2M words x 4 banks x 32 bits.

Accesses to the SDRAM are burst oriented. Consecutive memory location in one page can be accessed at a burst length of 1, 2, 4, 8 or full page when a bank and row is selected by an ACTIVE command. Column addresses are automatically generated by the SDRAM internal counter in burst operation. Random column read is also possible by providing its address at each clock cycle. The multiple bank nature enables interleaving among internal banks to hide the precharging time.

By having a programmable Mode Register, the system can change burst length, latency cycle, interleave or sequential burst to maximize its performance. PT480832BG is ideal for main memory in high performance applications.

2. FEATURES

3.3 V \pm 10% power supply

2,097,152 words x 4 banks x 32 bits organization

Auto and Self refresh

CAS latency: 2 and 3

Burst Length: 1, 2, 4, 8, and full page

Sequential and Interleave burst

Burst read, Single Write Operation

Byte data controlled by DQM

Power-down Mode

Auto-precharge and controlled precharge

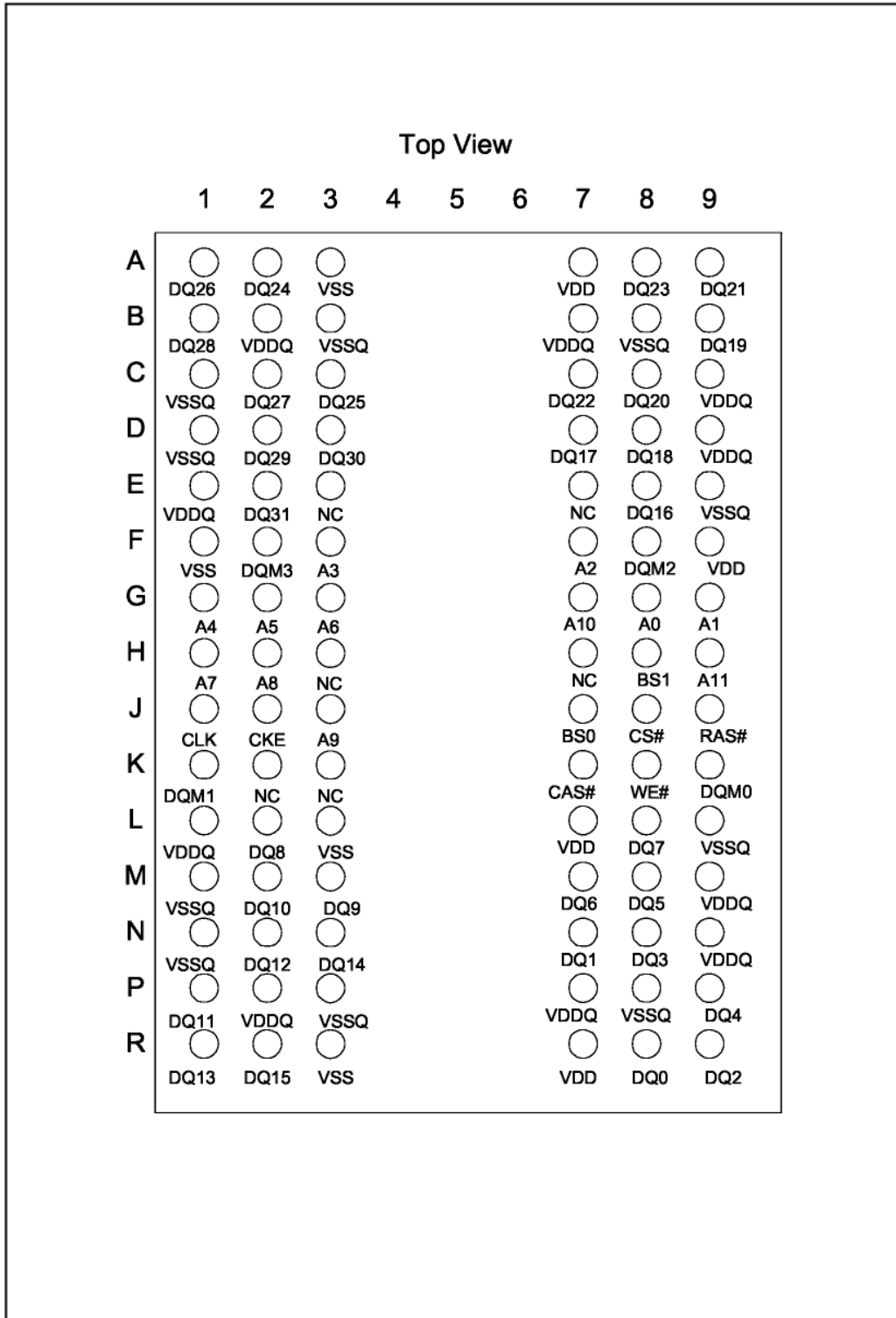
4K refresh cycles/64 mS

Interface: LVTTTL

Packaged in VFBGA 90 BALL, using PB free with RoHS compliant.

3. PART NUMBER INFORMATION

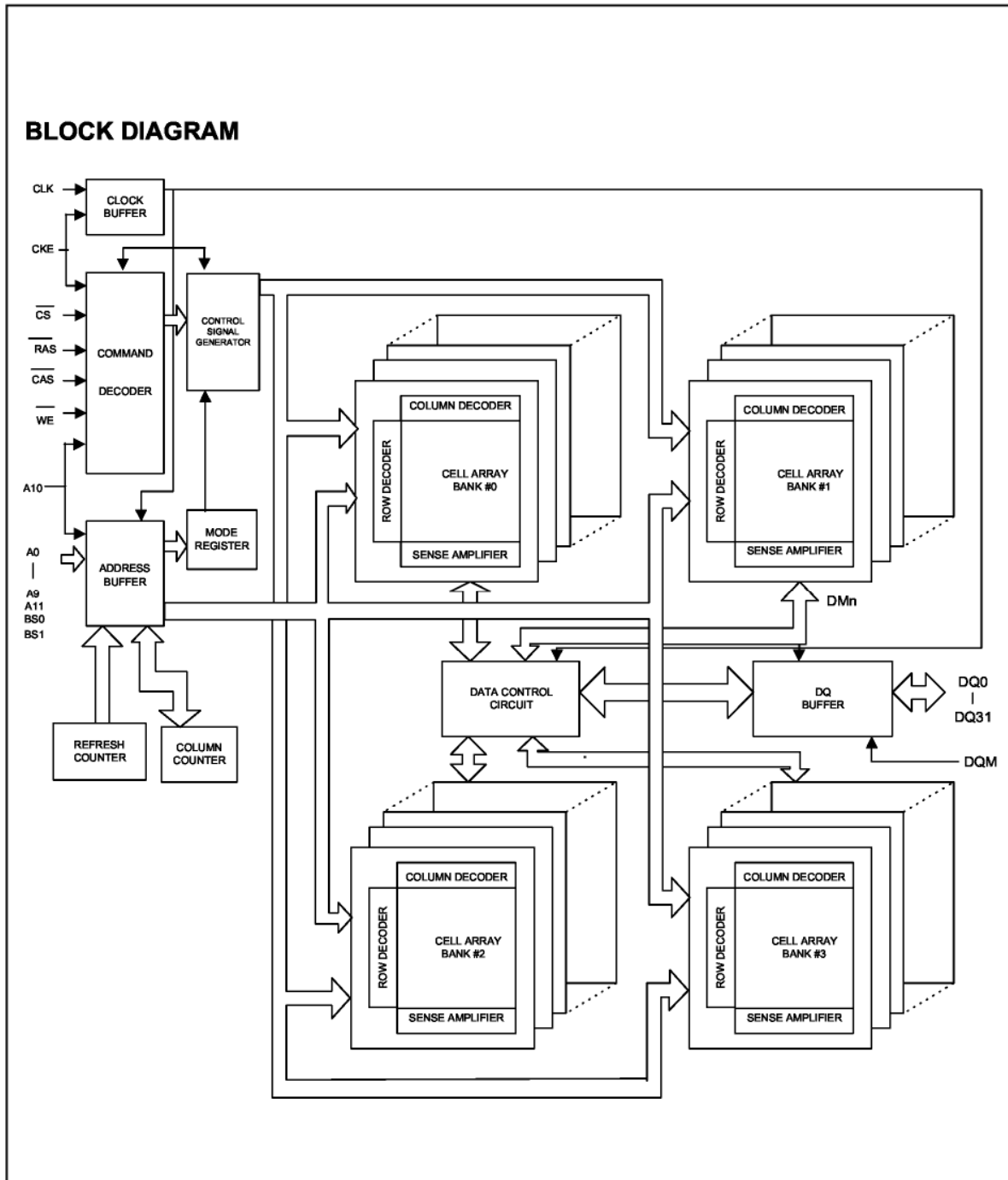
Part Number	Speed	Maximum Self Refresh Current	Operating Temperature
PT480832BG-6	166MHz/CL3	3 mA	0°C - 70°C
PT480832BG-75	133MHz/CL3	3 mA	0°C - 70°C

4. BALL CONFIGURATION


5. BALL DESCRIPTION

BALL LOCATION	PIN NAME	FUNCTION	DESCRIPTION
G8,G9,F7,F3,G1,G,G3,H1,H2,J3,G7,H9	A0-A11	Address	Multiplexed pins for row and column address. Row address:A0-A11. Column address: A0-A8.
J7,H8	BS0, BS1	Bank Select	Select bank to activate during row address latch time, or bank to read/write during address latch time.
A1,A2,A8,A9,B1,B9,C2,C3,C7,C8,D2,D3,D7,D8,E2,E8,L2,L8,M2,M3,M7,M8,N2,N3,N7,N8,P1,P9,R1,R2,R8,R9	DQ0-DQ31	Data Input/Output	Multiplexed pins for data output and input.
J8	CS	Chip Select	Disable or enable the command decoder. When command decoder is disabled, new command is ignored and previous operation continues.
J9	RAS	Row Address Strobe	Command input. When sampled at the rising edge of the clock RAS, CAS and WE define the operation to be executed.
K7	CAS	Column Address Strobe	Referred to RAS
K8	WE	Write Enable	Referred to RAS
F2,F8,K1,K9	DQM0~3	Input/output mask	The output buffer is placed at Hi-Z (with latency of 2) when DQM is sampled high in read cycle. In write cycle, sampling DQM high will block the write operation with zero latency.
J1	CLK	Clock Inputs	System clock used to sample inputs on the rising edge of clock.
J2	CKE	Clock Enable	CKE controls the clock activation and deactivation. When CKE is low, Power Down mode, Suspend mode, or Self Refresh mode is entered.
A7,F9,L7,R7	V _{DD}	Power (+3.3V)	Power for input buffers and logic circuit inside DRAM.
A3,F1,L3,R3	V _{SS}	Ground	Ground for input buffers and logic circuit inside DRAM.
B2,B7,C9,D9,E1,L1,M9,N9,P2,	V _{DDQ}	Power(+3.3V) for I/O buffer	Separated power from V _{DD} , to improve DQ noise immunity.
B8,B3,C1,D1,E9,L9,M1,N1,P8,	V _{SSQ}	Ground for I/O buffer	Separated ground from V _{SS} , to improve DQ noise immunity.
E3,E7,H3,H7,H9,K2,K3	NC	No Connection	No connection. (The NC pin must connect to ground or floating.)

6. BLOCK DIAGRAM



7. FUNCTIONAL DESCRIPTION

7.1 Power Up and Initialization

The default power up state of the mode register is unspecified. The following power up and initialization sequence need to be followed to guarantee the device being preconditioned to each user specific needs.

During power up, all V_{CC} and V_{CCQ} pins must be ramp up simultaneously to the specified voltage when the input signals are held in the "NOP" state. The power up voltage must not exceed $V_{CC} + 0.3V$ on any of the input pins or V_{CC} supplies. After power up, an initial pause of 200 μS is required followed by a precharge of all banks using the precharge command. To prevent data contention on the DQ bus during power up, it is required that the DQM and CKE pins be held high during the initial pause period. Once all banks have been precharged, the Mode Register Set Command must be issued to initialize the Mode Register. An additional eight Auto Refresh cycles (CBR) are also required before or after programming the Mode Register to ensure proper subsequent operation.

7.2 Programming Mode Register

After initial power up, the Mode Register Set Command must be issued for proper device operation. All banks must be in a precharged state and CKE must be high at least one cycle before the Mode Register Set Command can be issued. The Mode Register Set Command is activated by the low signals of RAS, CAS, CS and WE at the positive edge of the clock. The address input data during this cycle defines the parameters to be set as shown in the Mode Register Operation table. A new command may be issued following the mode register set command once a delay equal to t_{RSC} has elapsed. Please refer to the next page for Mode Register Set Cycle and Operation Table.

7.3 Bank Activate Command

The Bank Activate command must be applied before any Read or Write operation can be executed. The operation is similar to RAS activate in EDO DRAM. The delay from when the Bank Activate command is applied to when the first read or write operation can begin must not be less than the RAS to CAS delay time (t_{RCD}). Once a bank has been activated it must be precharged before another Bank Activate command can be issued to the same bank. The minimum time interval between successive Bank Activate commands to the same bank is determined by the RAS cycle time of the device (t_{RC}). The minimum time interval between interleaved Bank Activate commands (Bank A to Bank B and vice versa) is the Bank-to-Bank delay time (t_{RBD}). The maximum time that each bank can be held active is specified as $t_{RAS(max)}$.

7.4 Read and Write Access Modes

After a bank has been activated, a read or write cycle can be followed. This is accomplished by setting RAS high and CAS low at the clock rising edge after minimum of t_{RCD} delay. WE pin voltage level defines whether the access cycle is a read operation (WE high), or a write operation (WE low). The address inputs determine the starting column address. Reading or writing to a different row within an activated bank requires the bank be precharged and a new Bank Activate command be issued. When more than one bank is activated, interleaved bank Read or Write operations are possible. By using the programmed burst length and alternating the access and precharge operations between multiple banks, seamless data access operation among many different pages can be realized. Read or Write Commands can also be issued to the same bank or between active banks on every clock cycle.

7.5 Burst Read Command

The Burst Read command is initiated by applying logic low level to CS and CAS while holding RAS and WE high at the rising edge of the clock. The address inputs determine the starting column address for the burst. The Mode Register sets type of burst (sequential or interleave) and the burst length (1, 2, 4, 8, full page) during the Mode Register Set Up cycle.

7.6 Burst Write Command

The Burst Write command is initiated by applying logic low level to CS, CAS and WE while holding RAS high at the rising edge of the clock. The address inputs determine the starting column address. Data for the first burst write cycle must be applied on the DQ pins on the same clock cycle that the Write Command is issued. The remaining data inputs must be supplied on each subsequent rising clock edge until the burst length is completed. Data supplied to the DQ pins after burst finishes will be ignored.

7.7 Read Interrupted by a Read

A Burst Read may be interrupted by another Read Command. When the previous burst is interrupted, the remaining addresses are overridden by the new read address with the full burst length. The data from the first Read Command continues to appear on the outputs until the CAS latency from the interrupting Read Command is satisfied.

7.8 Read Interrupted by a Write

To interrupt a burst read with a Write Command, DQM may be needed to place the DQs (output drivers) in a high impedance state to avoid data contention on the DQ bus. If a Read Command will issue data on the first and second clocks cycles of the write operation, DQM is needed to insure the DQs are tri-stated. After that point the Write Command will have control of the DQ bus and DQM masking is no longer needed.

7.9 Write Interrupted by a Write

A burst write may be interrupted before completion of the burst by another Write Command. When the previous burst is interrupted, the remaining addresses are overridden by the new address and data will be written into the device until the programmed burst length is satisfied.

7.10 Write Interrupted by a Read

A Read Command will interrupt a burst write operation on the same clock cycle that the Read Command is activated. The DQs must be in the high impedance state at least one cycle before the new read data appears on the outputs to avoid data contention. When the Read Command is activated, any residual data from the burst write cycle will be ignored.

7.11 Burst Stop Command

A Burst Stop Command may be used to terminate the existing burst operation but leave the bank open for future Read or Write Commands to the same page of the active bank, if the burst length is full page. Use of the Burst Stop Command during other burst length operations is illegal. The Burst Stop Command is defined by having RAS and CAS high with CS and WE low at the rising edge of the clock. The data DQs go to a high impedance state after a delay, which is equal to the CAS Latency in a burst read cycle, interrupted by Burst Stop. If a Burst Stop Command is issued during a full page burst write operation, then any residual data from the burst write cycle will be ignored.

7.12 Addressing Sequence of Burst Type

The disturb address is varied by the Burst Length as shown in Table.

Burst Length	Starting Column Address			Order of Accesses Within a Burst		
				Type = Sequential	Type = Interleaved	
2	A0					
		0		0-1	0-1	
		1		1-0	1-0	
4	A1		A0			
		0	0	0-1-2-3	0-1-2-3	
		0	1	1-2-3-0	1-0-3-2	
		1	0	2-3-0-1	2-3-0-1	
		1	1	3-0-1-2	3-2-1-0	
8	A2	A1	A0			
		0	0	0-1-2-3-4-5-6-7	0-1-2-3-4-5-6-7	
		0	0	1	1-2-3-4-5-6-7-0	1-0-3-2-5-4-7-6
		0	1	0	2-3-4-5-6-7-0-1	2-3-0-1-6-7-4-5
		0	1	1	3-4-5-6-7-0-1-2	3-2-1-0-7-6-5-4
		1	0	0	4-5-6-7-0-1-2-3	4-5-6-7-0-1-2-3
		1	0	1	5-6-7-0-1-2-3-4	5-4-7-6-1-0-3-2
		1	1	0	6-7-0-1-2-3-4-5	6-7-4-5-2-3-0-1
	1	1	1	7-0-1-2-3-4-5-6	7-6-5-4-3-2-1-0	

7.13 Auto-precharge Command

If A10 is set to high when the Read or Write Command is issued, then the auto-precharge function is entered. During auto-precharge, a Read Command will execute as normal with the exception that the active bank will begin to precharge automatically before all burst read cycles have been completed. Regardless of burst length, it will begin a certain number of clocks prior to the end of the scheduled burst cycle. The number of clocks is determined by CAS latency.

A Read or Write Command with auto-precharge can not be interrupted before the entire burst operation is completed. Therefore, using of a Read, Write, or Precharge Command is prohibited during a read or write cycle with auto-precharge. Once the precharge operation has started, the bank cannot be reactivated until the Precharge time (t_{RP}) has been satisfied. Issue of Auto-Precharge command is illegal if the burst is set to full page length. If A10 is high when a Write Command is issued, the Write with Auto-Precharge function is initiated. The SDRAM automatically enters the precharge operation two clock delay from the last burst write cycle. This delay is referred to as Write t_{WR} . The bank undergoing auto-precharge can not be reactivated until t_{WR} and t_{RP} are satisfied. This is referred to as t_{DAL} , Data-in to Active delay ($t_{DAL} = t_{WR} + t_{RP}$). When using the Auto-precharge Command, the interval between the Bank Activate Command and the beginning of the internal precharge operation must satisfy t_{RAS} (min).

7.14 Precharge Command

The Precharge Command is used to precharge or close a bank that has been activated. The Precharge Command is entered when CS, RAS and WE are low and CAS is high at the rising edge of the clock. The Precharge Command can be used to precharge each bank separately or all banks simultaneously. The address bits, A10, BS0 and BS1 are used to define which bank(s) is to be precharged when the command is issued. After the Precharge Command is issued, the precharged bank must be reactivated before a new read or write access can be executed. The delay between the Precharge Command and the Activate Command must be greater than or equal to the Precharge time (t_{RP}).

7.15 Self Refresh Command

The Self-Refresh Command is defined by having CS, RAS, CAS and CKE held low with WE high at the rising edge of the clock. All banks must be idle prior to issuing the Self-Refresh Command. Once the command is registered, CKE must be held low to keep the device in Self-Refresh mode. When the SDRAM has entered Self Refresh mode all of the external control signals, except CKE, are disabled. The clock is internally disabled during Self-Refresh Operation to save power. The device will exit Self-Refresh operation after CKE is returned high. Any subsequent commands can be issued after t_{RC} from the end of Self Refresh command.

If, during normal operation, Auto-Refresh cycles are issued in bursts (as opposed to being evenly distributed), a burst of 4,096 Auto-Refresh cycles should be completed just prior to entering and just after exiting the Self-Refresh mode.

7.16 Power Down Mode

The Power Down mode is initiated by holding CKE low. All of the receiver circuits except CKE are gated off to reduce the power. The Power Down mode does not perform any refresh operations; therefore the device can not remain in Power Down mode longer than the Refresh period (t_{REF}) of the device.

The Power Down mode is exited by bringing CKE high. When CKE goes high, a No Operation Command is required on the next rising clock edge, depending on t_{CK} . The input buffers need to be enabled with CKE held high for a period equal to $t_{CKS}(\text{min}) + t_{CK}(\text{min})$.

7.17 No Operation Command

The No Operation Command should be used in cases when the SDRAM is in an idle or a wait state to prevent the SDRAM from registering any unwanted commands between operations. A No Operation Command is registered when CS is low with RAS, CAS, and WE held high at the rising edge of the clock. A No Operation Command will not terminate a previous operation that is still executing, such as a burst read or write cycle.

7.18 Deselect Command

The Deselect Command performs the same function as a No Operation Command. Deselect Command occurs when CS is brought high, the RAS, CAS, and WE signals become don't cares.

7.19 Clock Suspend Mode

During normal access mode, CKE must be held high enabling the clock. When CKE is registered low while at least one of the banks is active, Clock Suspend Mode is entered. The Clock Suspend mode deactivates the internal clock and suspends any clocked operation that was currently being executed. There is a one-clock delay between the registration of CKE low and the time at which the SDRAM operation suspends. While in Clock Suspend mode, the SDRAM ignores any new commands that are issued. The Clock Suspend mode is exited by bringing CKE high. There is a one-clock cycle delay from when CKE returns high to when Clock Suspend mode is exited.

8. TABLE OF OPERATING MODES

Fully synchronous operations are performed to latch the commands at the positive edges of CLK. Table 1 shows the truth table for the operation commands.

TABLE 1 TRUTH TABLE (NOTE 1, 2)

COMMAND	DEVICE STATE	CKEN-1	CKEN	DQM	BS0,1	A10	A9-0 A11	CS	RAS	CAS	WE
Bank Active	Idle	H	X	X	V	V	V	L	L	H	H
Bank Precharge	Any	H	X	X	V	L	X	L	L	H	L
Precharge All	Any	H	X	X	X	H	X	L	L	H	L
Write	Active(3)	H	X	X	V	L	V	L	H	L	L
Write with Autoprecharge	Active(3)	H	X	X	V	H	V	L	H	L	L
Read	Active(3)	H	X	X	V	L	V	L	H	L	H
Read with Autoprecharge	Active(3)	H	X	X	V	H	V	L	H	L	H
Mode Register Set	Idle	H	X	X	V	V	V	L	L	L	L
No-Operation	Any	H	X	X	X	X	X	L	H	H	H
Burst Stop	Active (4)	H	X	X	X	X	X	L	H	H	L
Device Deselect	Any	H	X	X	X	X	X	H	X	X	X
Auto-Refresh	Idle	H	H	X	X	X	X	L	L	L	H
Self-Refresh Entry	Idle	H	L	X	X	X	X	L	L	L	H
Self-Refresh Exit	Idle (S.R)	L L	H H	X X	X X	X X	X X	H L	X H	X H	X X
Clock Suspend Mode Entry	Active	H	L	X	X	X	X	X	X	X	X
Power Down Mode Entry	Idle Active (5)	H H	L L	X X	X X	X X	X X	H L	X H	X H	X X
Clock Suspend Mode Exit	Active	L	H	X	X	X	X	X	X	X	X
Power Down Mode Exit	Any (Power down)	L L	H H	X X	X X	X X	X X	H L	X H	X H	X X
Data Write/Output Enable	Active	H	X	L	X	X	X	X	X	X	X
Data Write/Output Disable	Active	H	X	H	X	X	X	X	X	X	X

Notes:

(1) V = Valid, X = Don't care, L = Low Level, H = High Level

(2) CKEn signal is input level when commands are provided.

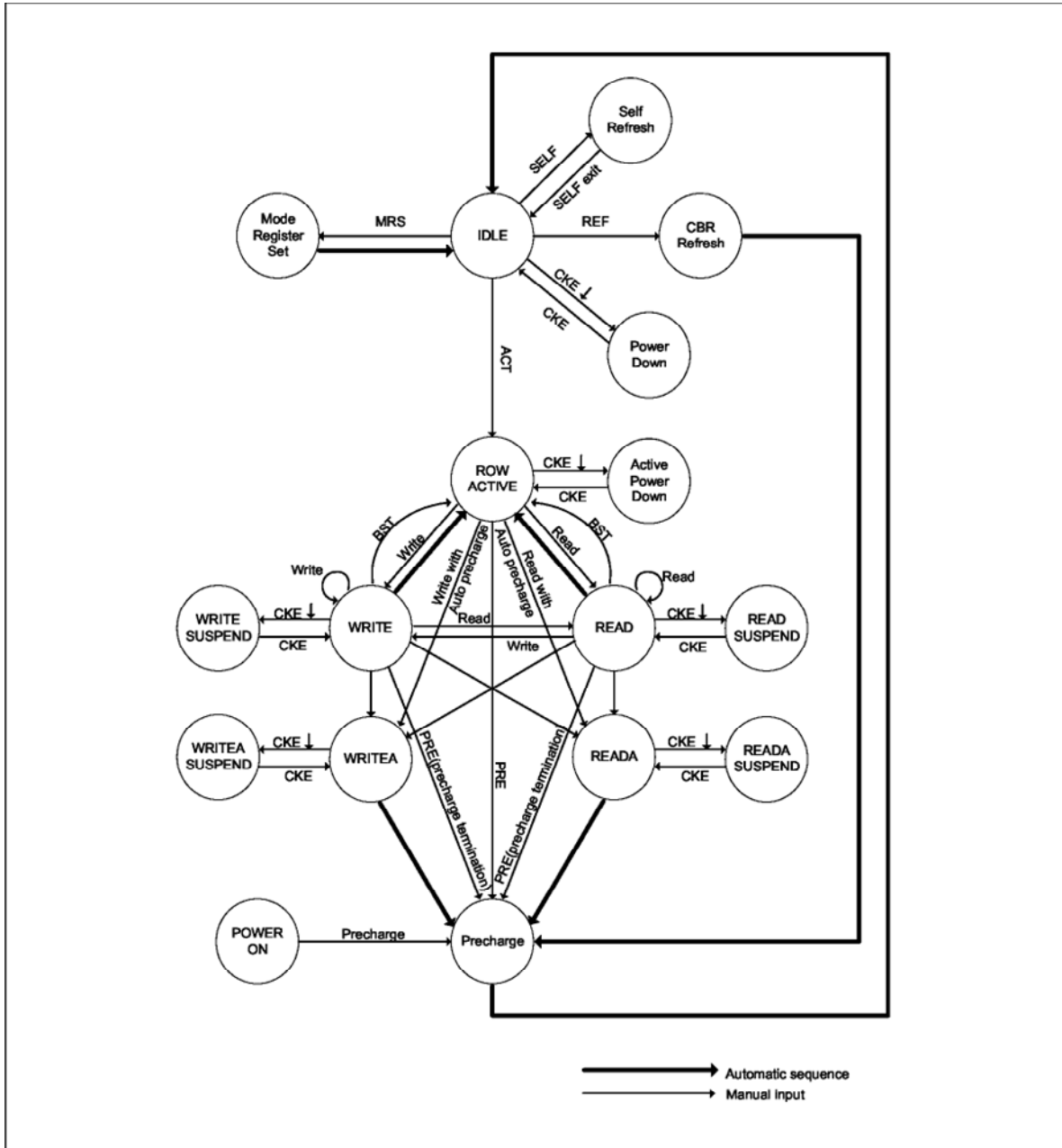
(3) These are state of bank designated by BS0,BS1 signals.

(4) Device state is full page burst operation.

(5) Power Down Mode can not be entered in the burst cycle.

When this command asserts in the burst cycle, device state is clock suspend mode.

8.1 Simplified State Diagram



Notes:

- MRS = Mode Register Set
- REF = Refresh
- ACT = Active
- PRE = Precharge
- WRITEA = Write with Auto Precharge
- READA = Read with Auto Precharge

9. ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	RATING	UNIT	NOTES
Input, Output Voltage	V_{IN}, V_{OUT}	$-0.3 - V_{CC} + 0.3$	V	1
Power Supply Voltage	V_{CC}, V_{CCQ}	$-0.3 - 4.6$	V	1
Operating Temperature	T_{OPR}	0 – 70	°C	1
Storage Temperature	T_{STG}	-55 – 150	°C	1
Soldering Temperature (10s)	T_{SOLDER}	260	°C	1
Power Dissipation	P_D	1	W	1
Short Circuit Output Current	I_{OUT}	50	mA	1

Note: Exposure to conditions beyond those listed under Absolute Maximum Ratings may adversely affect the life and reliability of the device.

10. RECOMMENDED DC OPERATING CONDITIONS

($T_A = 0$ to 70°C)

PARAMETER	SYM.	MIN.	TYP.	MAX.	UNIT	NOTES
Power Supply Voltage	V_{CC}	3.0	3.3	3.6	V	
Power Supply Voltage (for I/O Buffer)	V_{CCQ}	3.0	3.3	3.6	V	
Input High Voltage	V_{IH}	2.0	-	$V_{CC} + 0.3$	V	1
Input Low Voltage	V_{IL}	-0.3	-	0.8	V	2
Output logic high Voltage	V_{OH}	2.4			V	$I_{OH} = -2\text{mA}$
Output logic low Voltage	V_{OL}			0.4	V	$I_{OL} = 2\text{mA}$
Input leakage Current	I_{LI}	-10		10	μA	3

Note: (1) $V_{IH}(\text{max.}) = V_{CC}/V_{CCQ} + 1.2\text{V}$ for pulse width $< 5\text{ nS}$

(2) $V_{IL}(\text{min.}) = V_{SS}/V_{SSQ} - 1.2\text{V}$ for pulse width $< 5\text{ nS}$

(3) Any input $0\text{V} \leq V_{IN} \leq V_{CCQ}$ · Input leakage currents include Hi-Z output leakage for all bi-directional buffers with Tri-State outputs.

11 CAPACITANCE

($V_{CC} = 2.7\text{V} - 3.6\text{V}$, $T_A = 25\text{ C}$, $f = 1\text{MHz}$)

PARAMETER	SYM.	MIN.	MAX.	UNIT
Input Capacitance (A0 to A11, BS0, BS1, CS, RAS, CAS, WE, DQM, CKE)	C_{I1}	-	3.8	pf
Input Capacitance (CLK)	C_{CLK}	-	3.5	pf
Input/Output capacitance (DQ0 to DQ31)	C_{IO}	-	6.5	pf

Note: These parameters are periodically sampled and not 100% tested

12. DC CHARACTERISTICS
 $(V_{CC} = 3.3V \pm 0.3V, T_A = 0^\circ \sim 70^\circ C)$

PARAMETER		SYM.	-6 MAX.	-75 MAX.	UNIT	NOTES
Operating Current $t_{CK} = \text{min.}, t_{RC} = \text{min.}$ Active precharge command cycling without burst operation	1 bank operation	ICC1	140	120	mA	3
	Standby Current $t_{CK} = \text{min.}, CS = V_{IH}$ $V_{IH/L} = V_{IH} (\text{min.}) / V_{IL} (\text{max.})$ Bank: inactive state	CKE = V_{IH}	ICC2	50		35
Standby Current CLK = $V_{IL}, CS = V_{IH}$ $V_{IH/L} = V_{IH} (\text{min.}) / V_{IL} (\text{max.})$ Bank: inactive state	CKE = V_{IL} (Power down mode)	ICC2P	2	2		3
	CKE = V_{IH}	ICC2S	10	10		
No Operating Current $t_{CK} = \text{min.}, CS = V_{IH} (\text{min.})$ Bank: active state (2 banks)	CKE = V_{IL} (Power down mode)	ICC2PS	2	2		
	CKE = V_{IH}	ICC3	70	60		
Burst Operating Current ($t_{CK} = \text{min.}$) Read/ Write command cycling	CKE = V_{IL} (Power Down mode)	ICC3P	10	10		
		ICC4	200	170		3, 4
Auto Refresh Current ($t_{CK} = \text{min.}$) Auto refresh command cycling		ICC5	270	250		3
Self Refresh Current (CKE = 0.2V) Self refresh mode	Standard	ICC6	3	3		

PARAMETER	SYM.	MIN.	MAX.	UNIT	NOTES
Input Leakage Current ($0V \leq V_{IN} \leq V_{CC}$, all other pins not under test = 0V)	$I_{I(L)}$	-5	5	μA	
Output Leakage Current (Output disable, $0V \leq V_{OUT} \leq V_{CCQ}$)	$I_{O(L)}$	-5	5	μA	
LVTTL Output "H" Level Voltage ($I_{OUT} = -2 \text{ mA}$)	V_{OH}	2.4	-	V	
LVTTL Output "L" Level Voltage ($I_{OUT} = 2 \text{ mA}$)	V_{OL}	-	0.4	V	

13. AC CHARACTERISTICS

 (V_{CC} = 3.3V±0.3V, V_{SS} = 0V, T_A = 0 to 70°C, Notes: 5, 6, 7, 8)

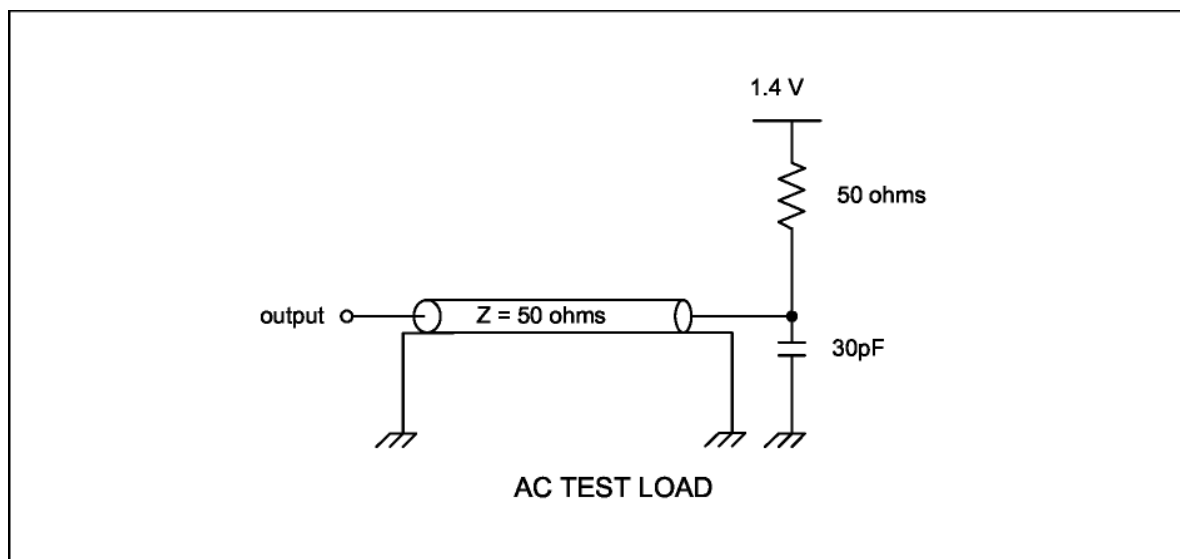
PARAMETER	SYM.	-6		-75		UNIT	NOTES
		MIN.	MAX.	MIN.	MAX.		
Ref/Active to Ref/Active Command Period	t _{RC}	60		65		nS	
Active to Precharge Command Period	t _{RAS}	42	100000	45	100000		
Active to Read/Write Command Delay Time	t _{RCD}	18		20			
Read/Write(a) to Read/Write(b) Command Period	t _{CCD}	1		1		t _{CK}	
Precharge to Active(b) Command Period	t _{RP}	18		20		nS	
Active(a) to Active(b) Command Period	t _{RPD}	12		15			
Write Recovery Time	t _{WR}	(CL=2)	2		2	t _{CK}	
		(CL=3)	2		2		
CLK Cycle Time	t _{CK}	(CL=2)	10	1000	10	1000	
		(CL=3)	6	1000	7.5	1000	
CLK High Level Width	t _{CH}	2		2.5			7
CLK Low Level Width	t _{CL}	2		2.5			7
Access Time from CLK	t _{AC}	(CL=2)		6		6	
		(CL=3)		5		5.4	
Output Data Hold Time	t _{OH}	3		3			
Output Data High Impedance Time	t _{HZ}	3	5.4	3	6		
Output Data Low Impedance Time	t _{LZ}	0		0			
Power Down Mode Entry Time	t _{SB}	0	6	0	7.5	nS	
Transition Time of CLK (Rise and Fall)	t _T	0.5	1	0.5	1		
Data-in-Set-up Time	t _{DS}	1.5		1.5			7
Data-in Hold Time	t _{DH}	1		1			7
Address Set-up Time	t _{AS}	1.5		1.5			7
Address Hold Time	t _{AH}	1		1			7
CKE Set-up Time	t _{CKS}	1.5		1.5			7
CKE Hold Time	t _{CKH}	1		1			7
Command Set-up Time	t _{CMS}	1.5		1.5			7
Command Hold Time	t _{CMH}	1		1			7
Refresh Time	t _{REF}		64		64	mS	
Mode Register Set Cycle Time	t _{RSC}	12		15		nS	

(L):For low power

Notes:

- (1) Operation exceeds "ABSOLUTE MAXIMUM RATING" may cause permanent damage to the devices.
- (2) All voltages are referenced to VSS
- (3) These parameters depend on the cycle rate and listed values are measured at a cycle rate with the minimum values of tCK and tRC.
- (4) These parameters depend on the output loading conditions. Specified values are obtained with output open.
- (5) Power up sequence
 - (1) Power up must be performed in the following sequence.
 - (2) Power must be applied to VCC and VCCQ (simultaneously) while all input signals are held in the "NOP" state. The CLK signals must be started at the same time.
 - (3) After power-up a pause of at least 200 μ seconds is required. It is required that DQM and CKE signals then be held "high" (VCC levels) to ensure that the DQ output is impedance.
 - (4) All banks must be precharged.
 - (5) The Mode Register Set command must be asserted to initialize the Mode Register.
 - (6) A minimum of eight Auto Refresh dummy cycles is required to stabilize the internal circuitry of the device.
- (6) AC test conditions.

PARAMETER	CONDITIONS
Output Reference Level	1.4V/1.4V
Output Load	See diagram below
Input Signal Levels	2.4V/0.4V
Transition Time (Rise and Fall) of Input Signal	2 nS
Input Reference Level	1.4V

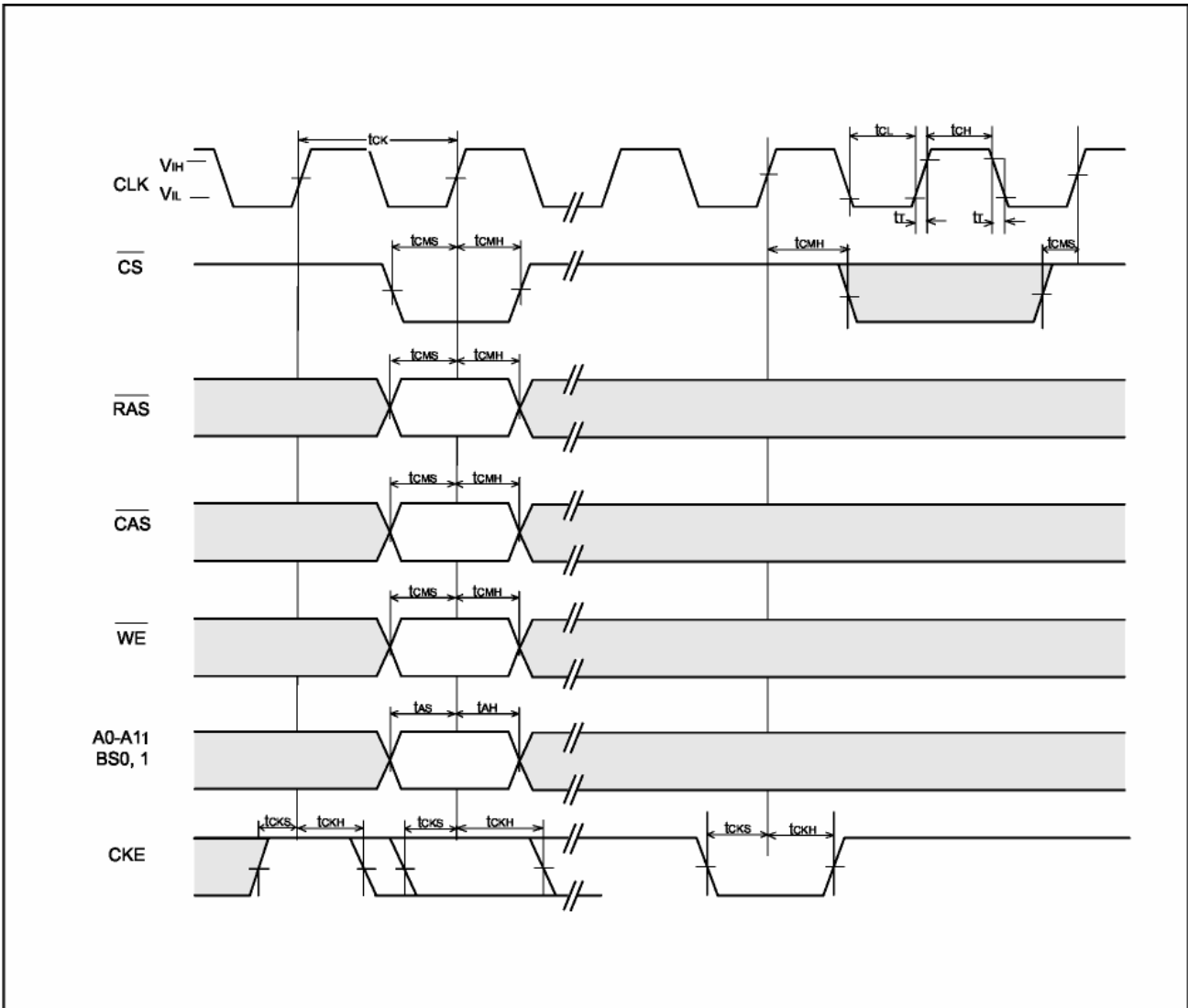


- 1. Transition times are measured between VIH and VIL.
- 2. This defines the time at which the outputs achieve the open circuit condition and is not referenced to output level.
- 3. These parameters account for the number of clock cycles and depend on the operating frequency of the clock, as follows the number of clock cycles = specified value of timing/ clock period (count fractions as whole number)
 - (1) Tch is the pulse width of CLK measured from the positive edge to the negative edge referenced to VIH (min.).

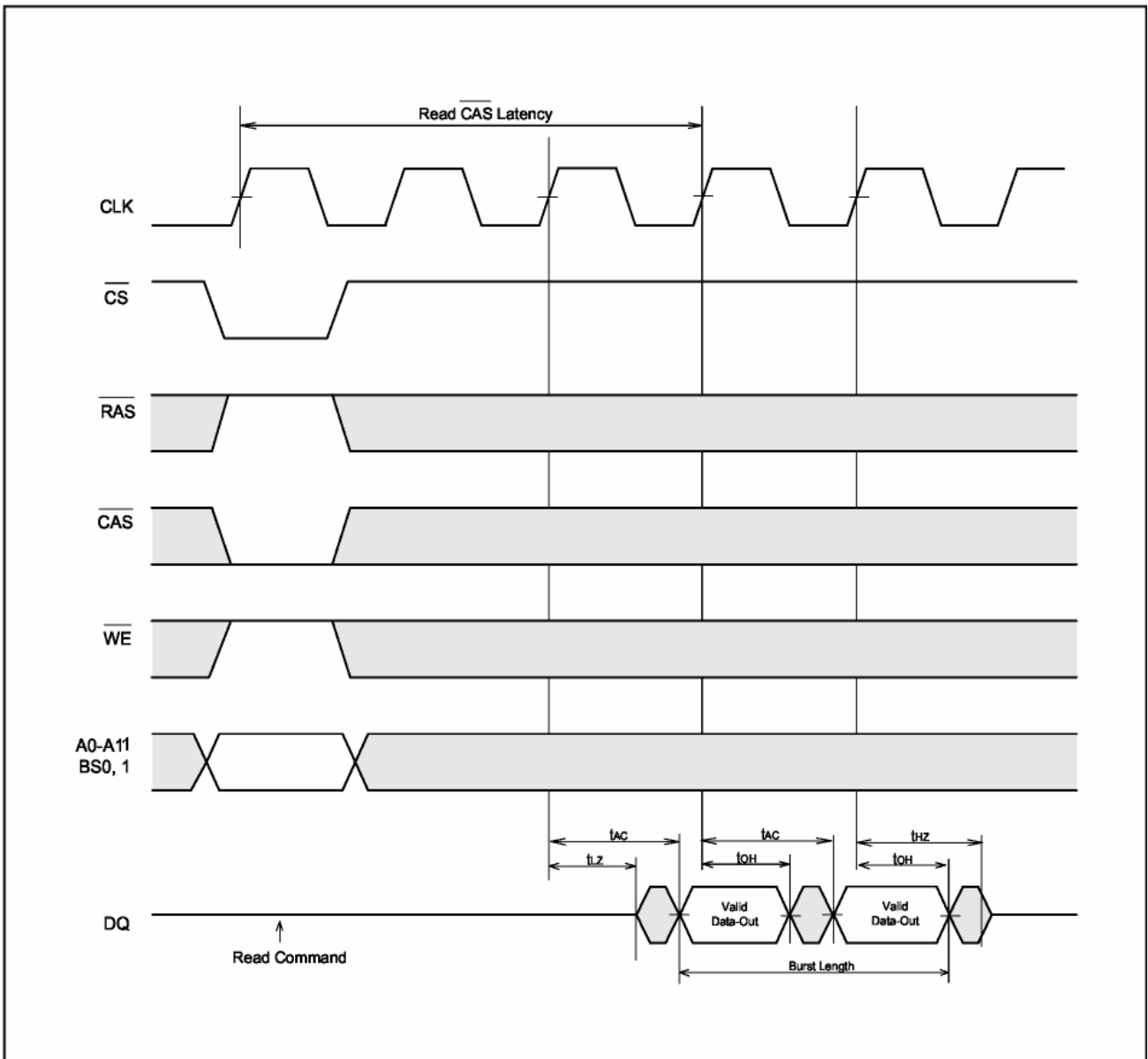
t_{cl} is the pulse width of CLK measured from the negative edge to the positive edge referenced to V_{IL} (max.)

14. TIMING WAVEFORMS

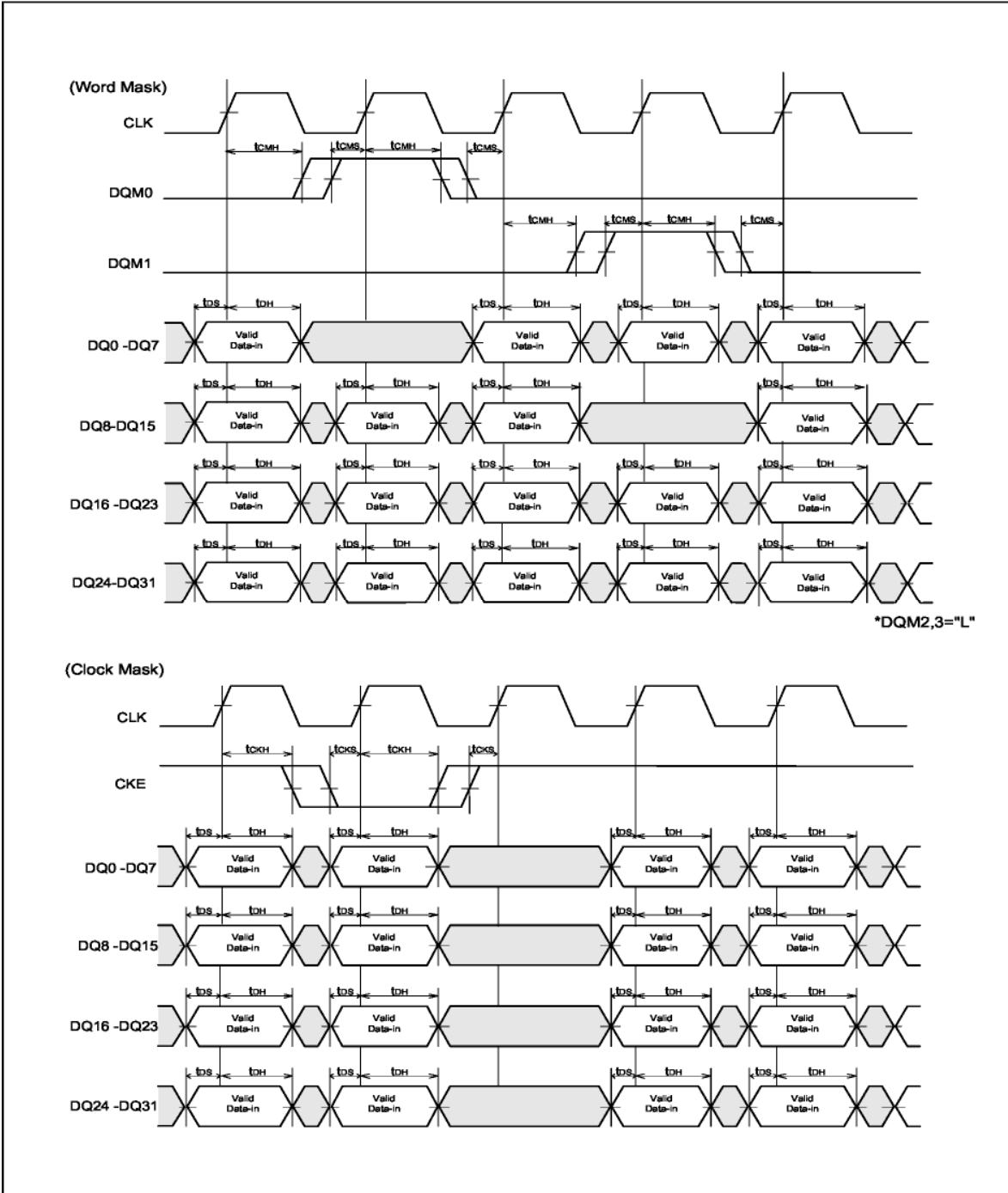
14.1 Command Input Timing



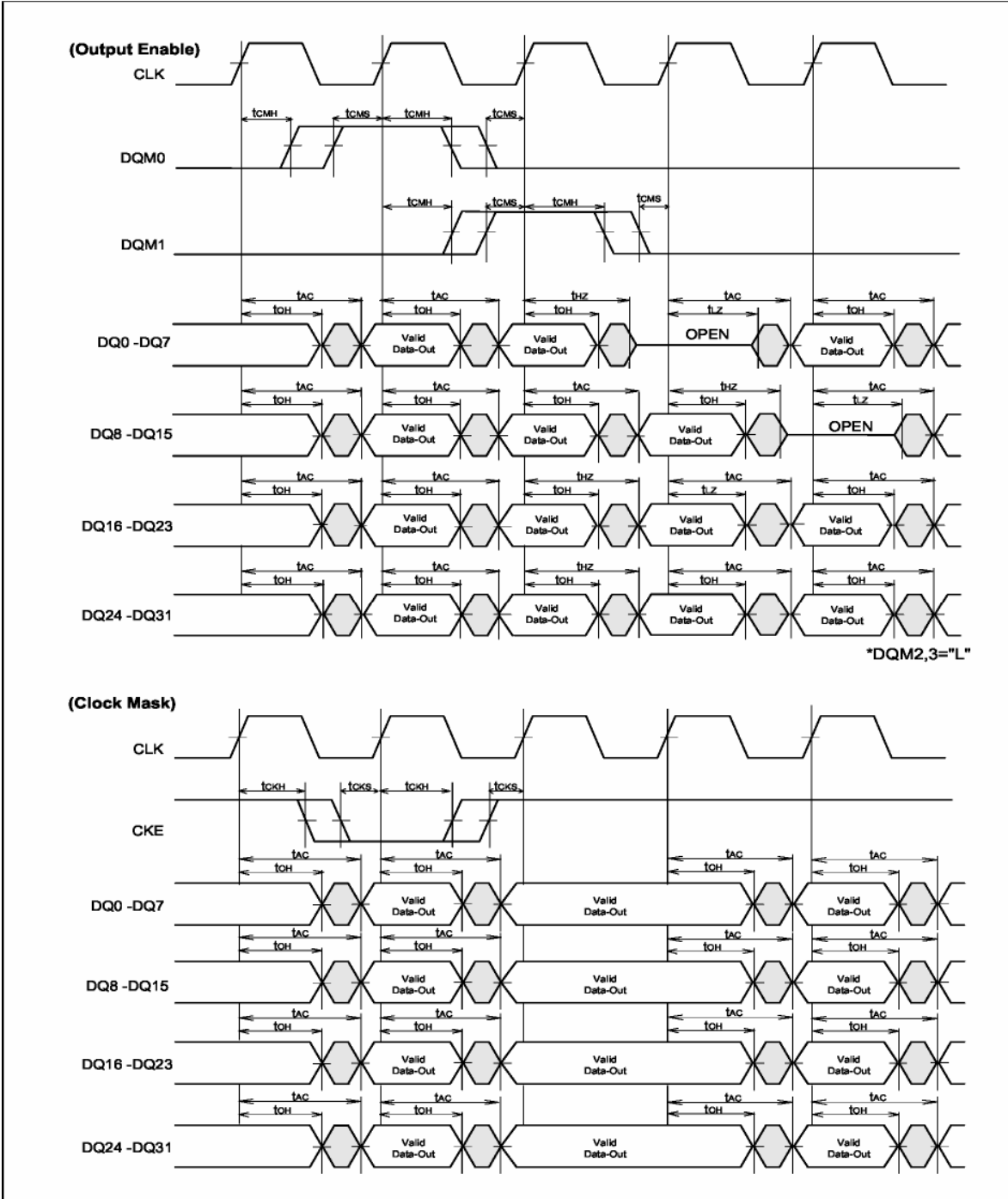
14.2 Read Timing



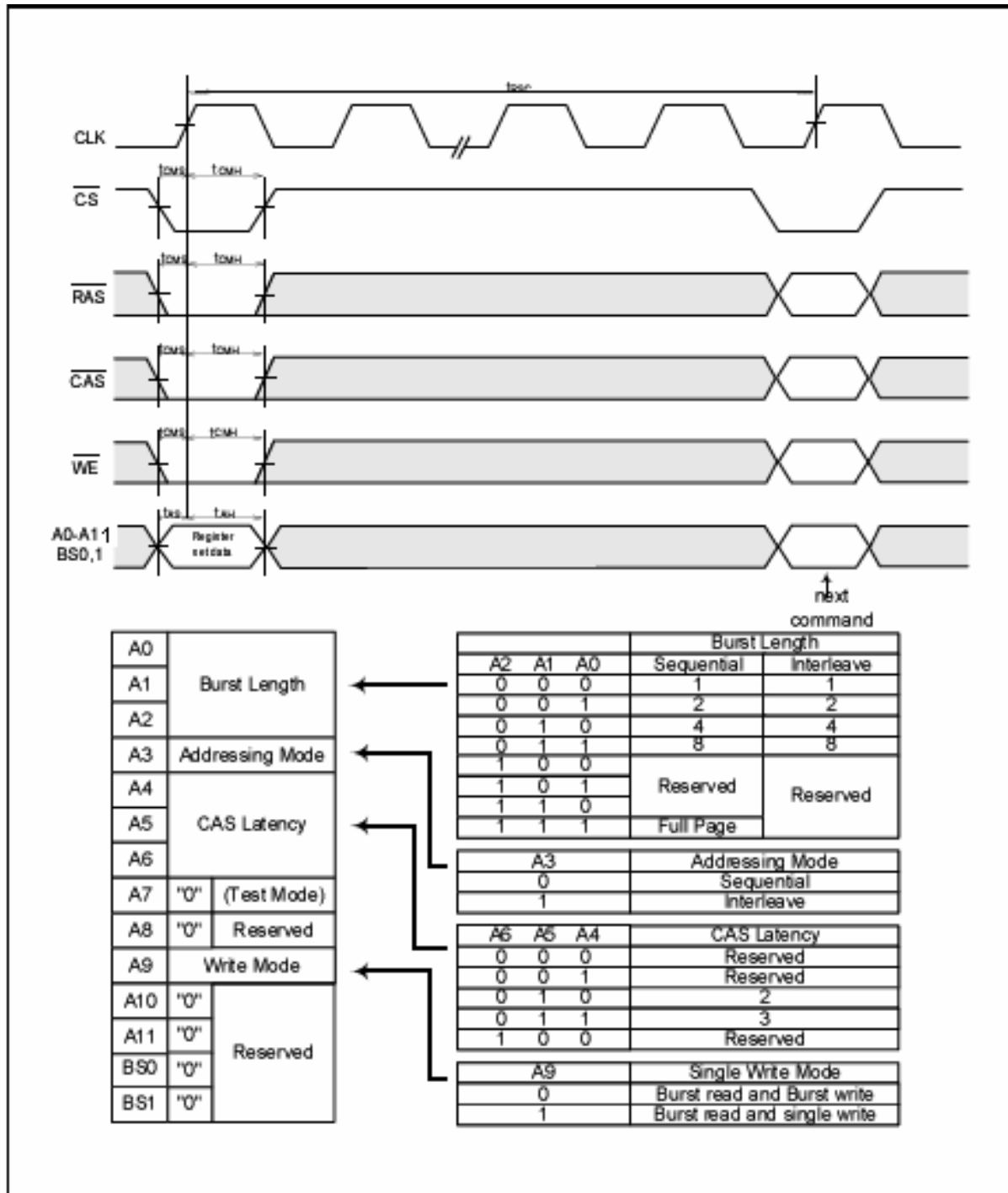
14.3 Control Timing of Input Data



14.4 Control Timing of Output Data

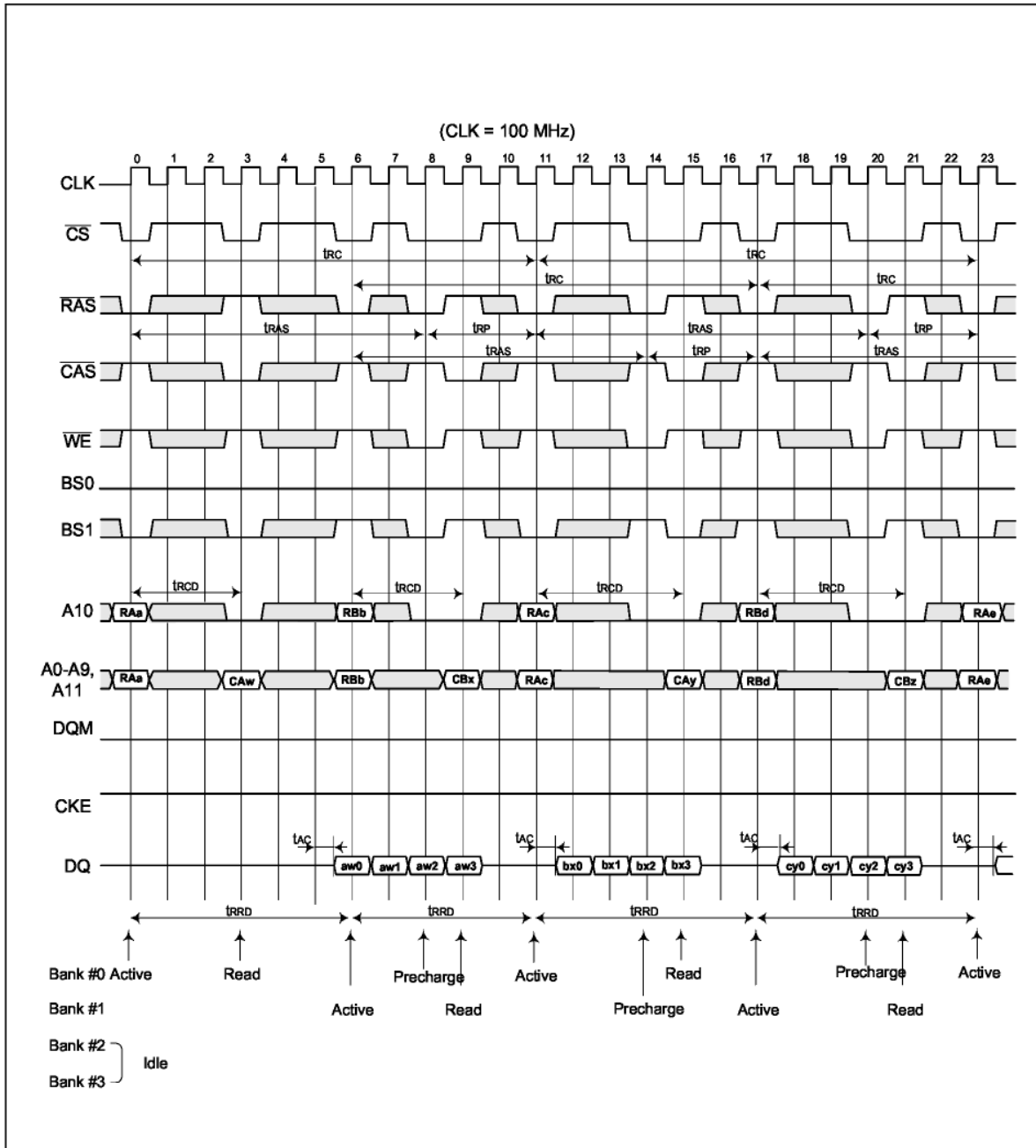


14.5 Mode Register Set Cycle



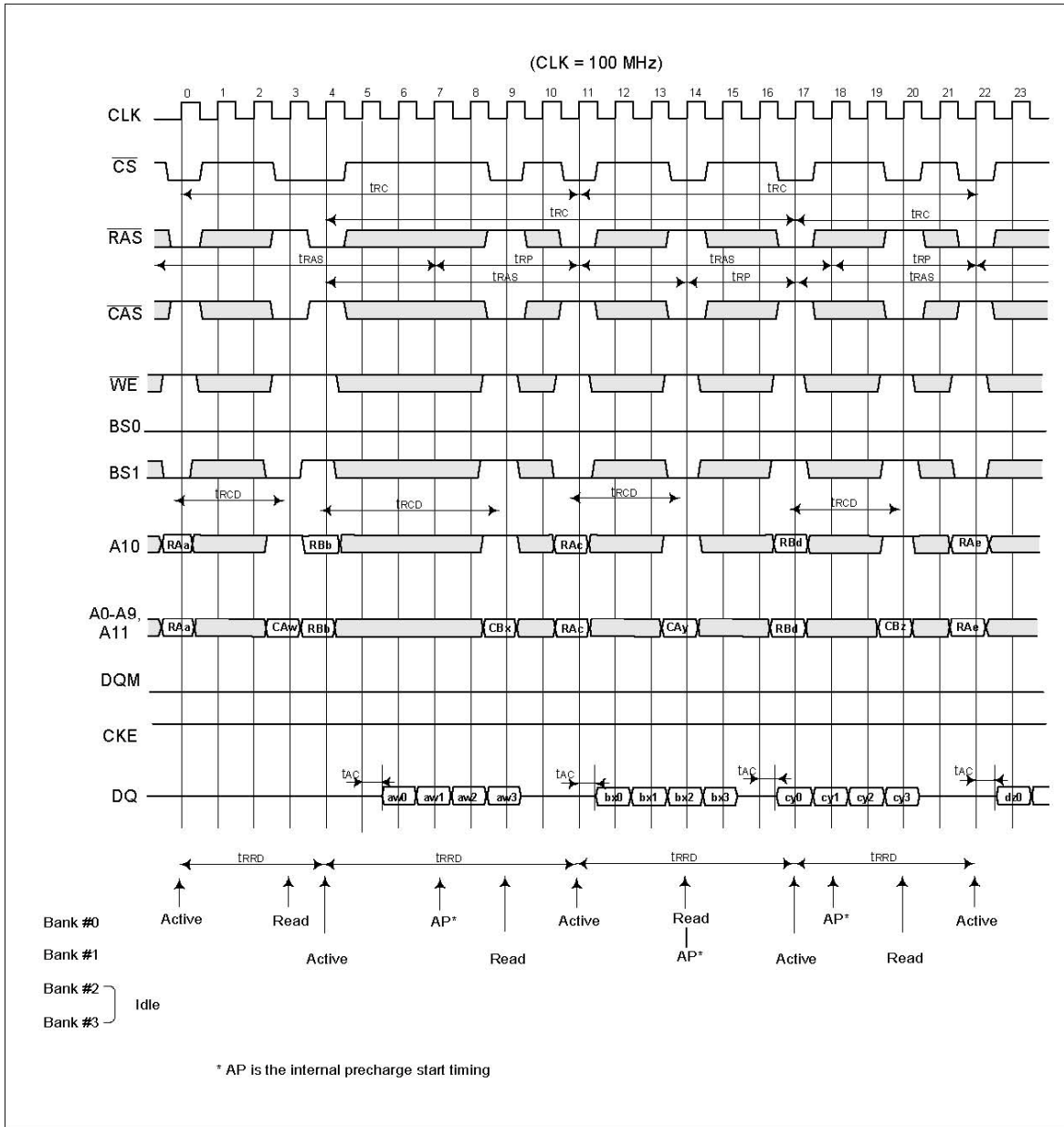
14.6 Interleaved Bank Read

(Burst Length = 4, CAS Latency = 3)



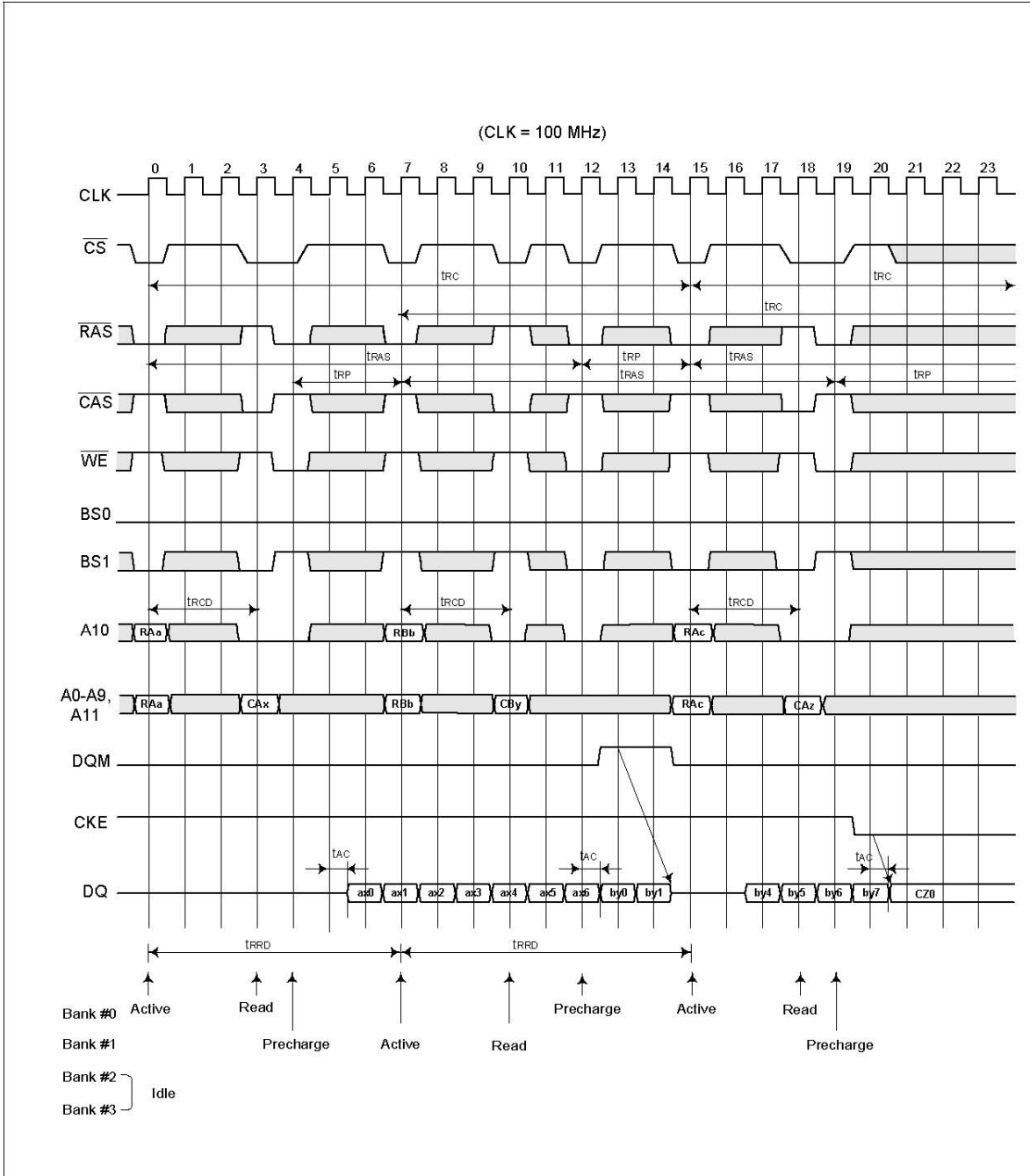
14.7 Interleaved Bank Read

(Burst Length = 4, CAS Latency = 3, Autoprecharge)



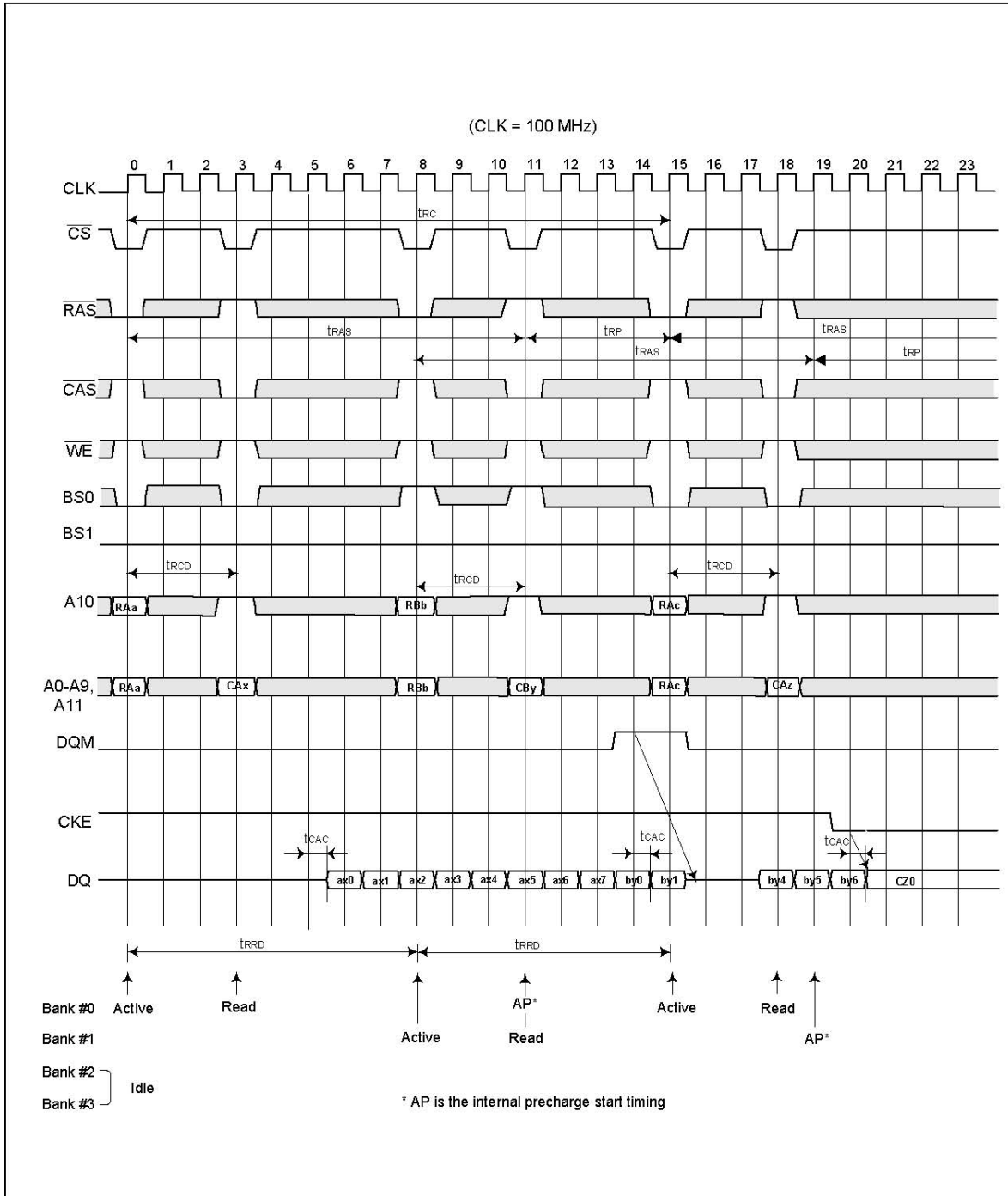
14.8 Interleaved Bank Read

(Burst Length = 8, CAS Latency = 3)



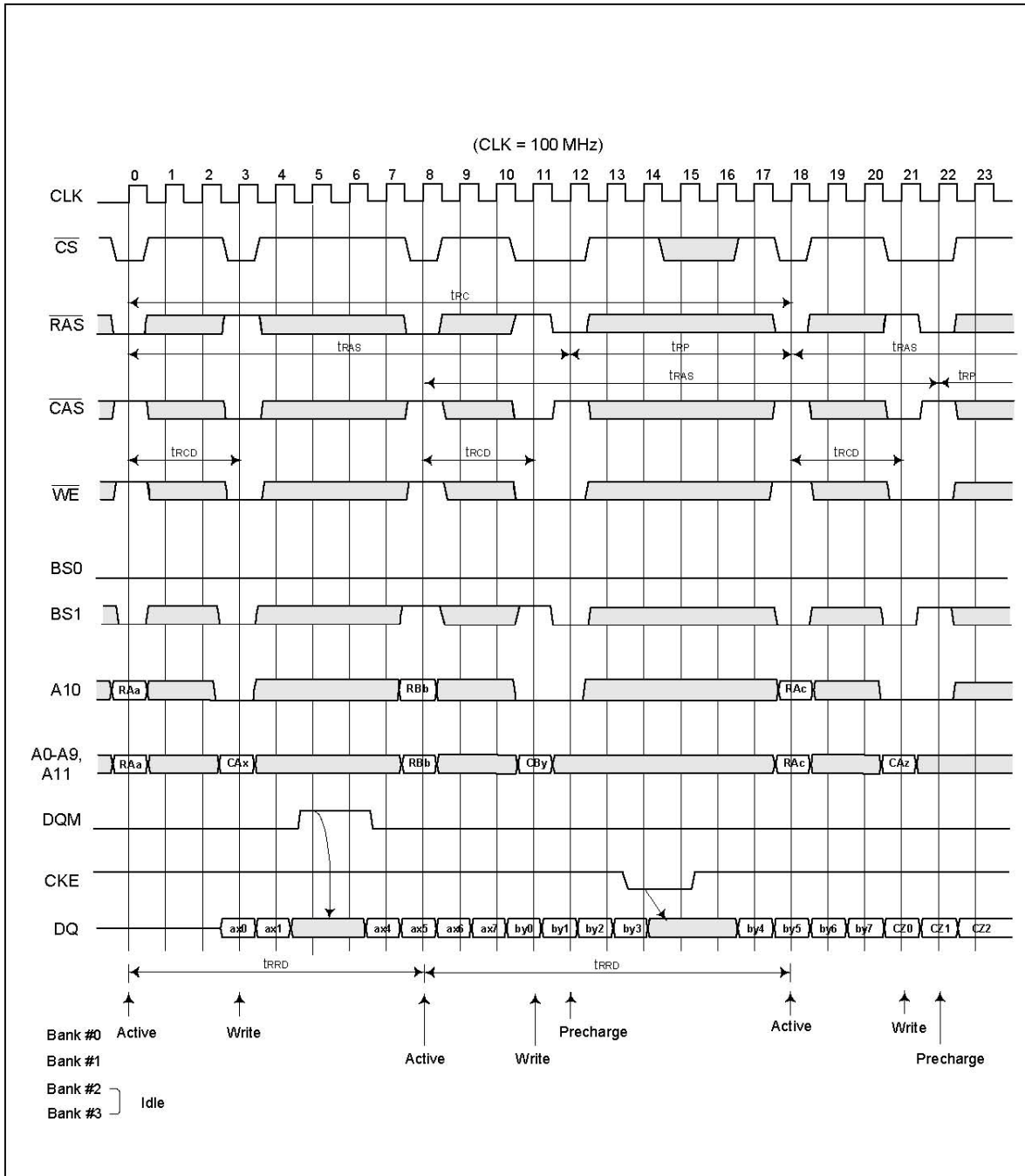
14.9 Interleaved Bank Read

(Burst Length = 8, CAS Latency = 3, Autoprecharge)



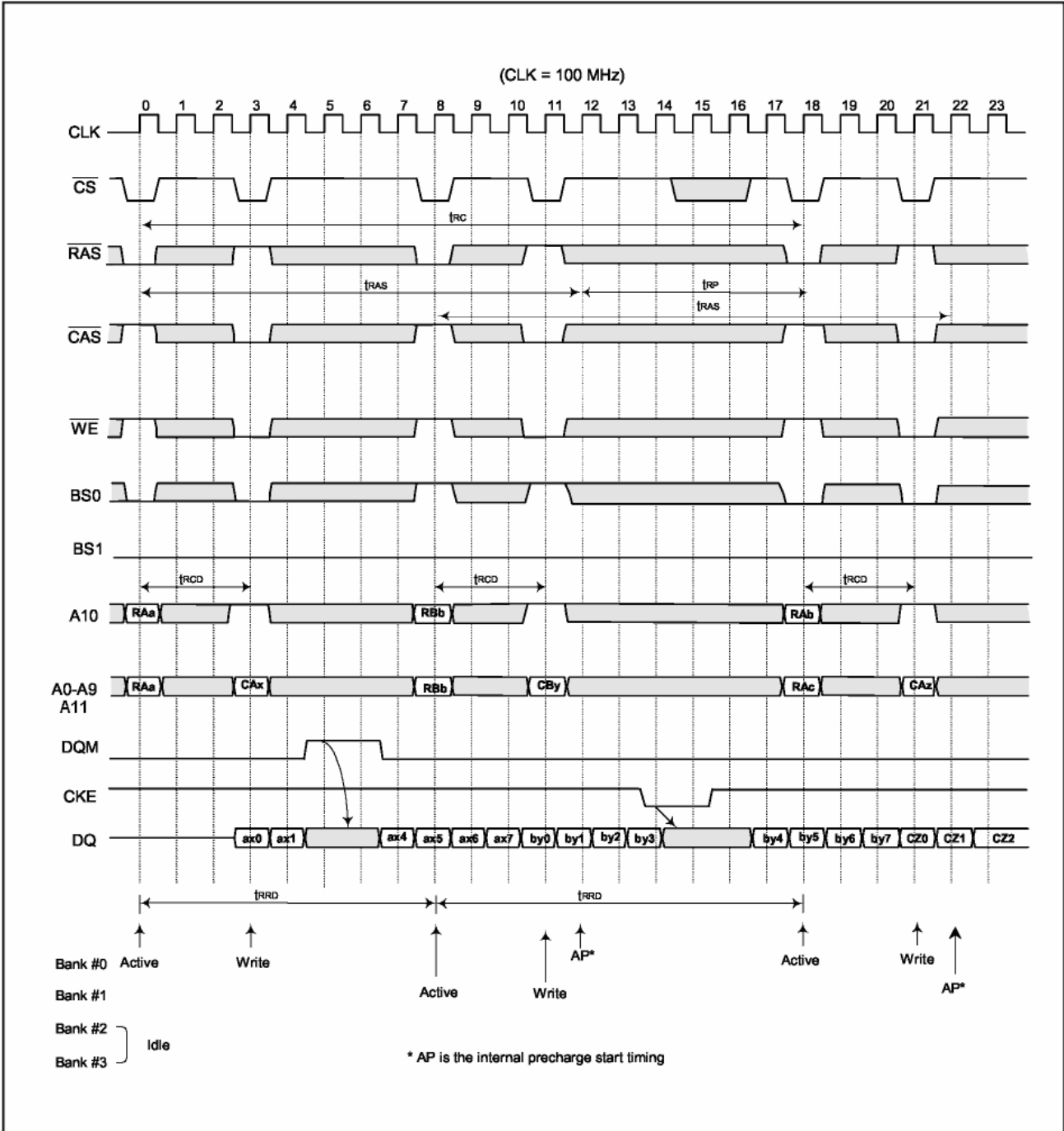
14.10 Interleaved Bank Write

(Burst Length = 8)



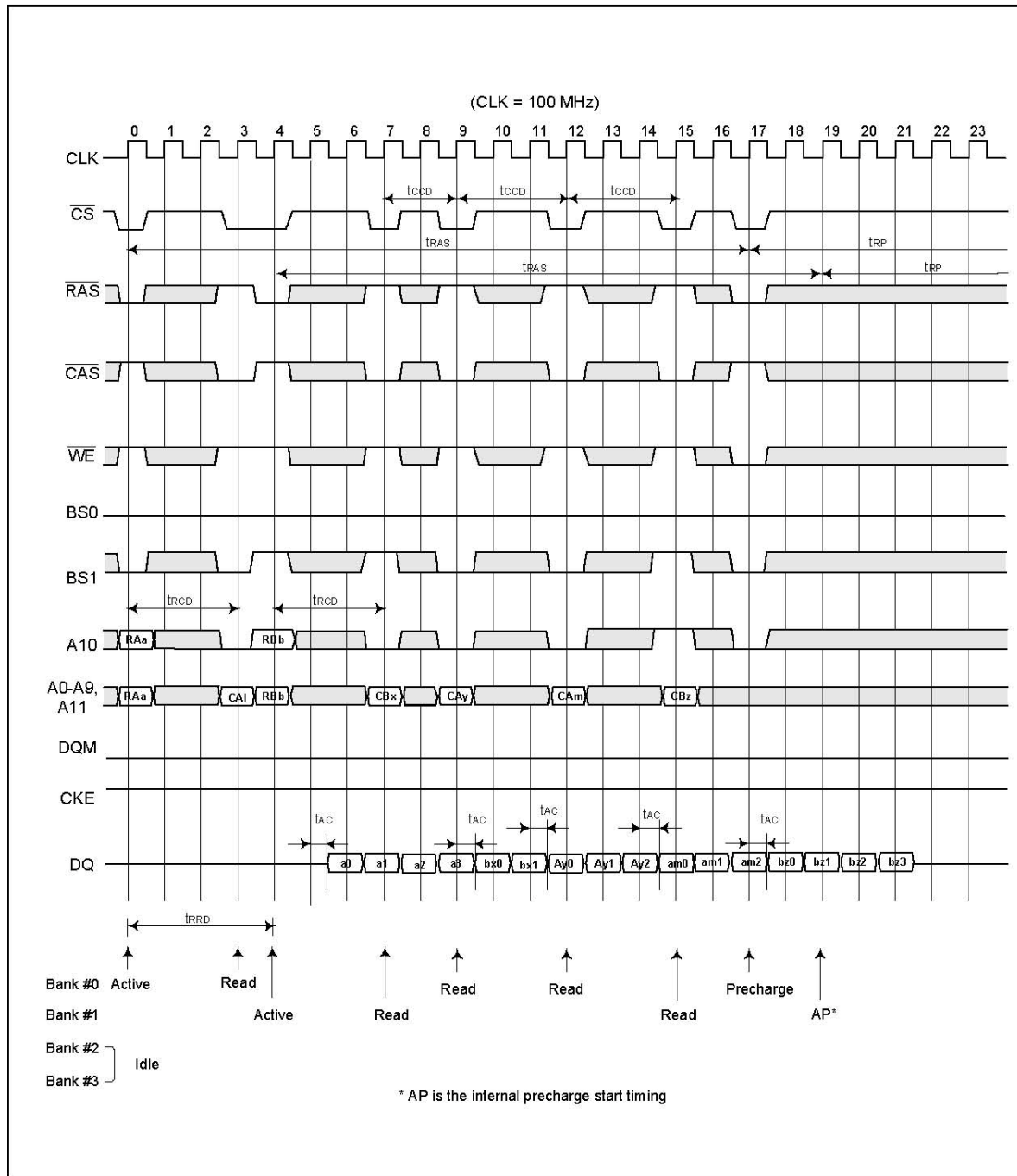
14.11 Interleaved Bank Write

(Burst Length = 8, Autoprecharge)



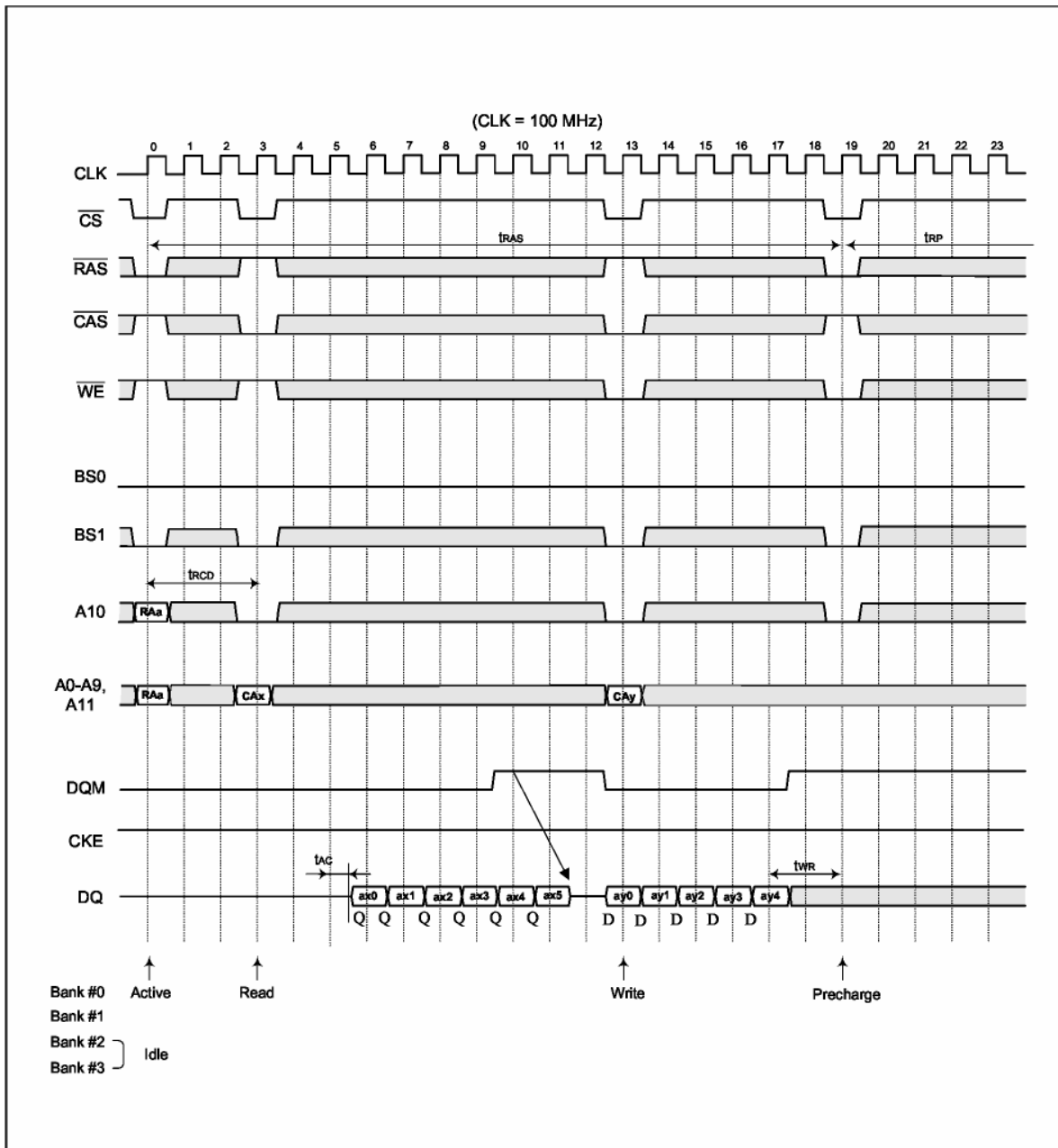
14.12 Page Mode Read

(Burst Length = 4, CAS Latency = 3)



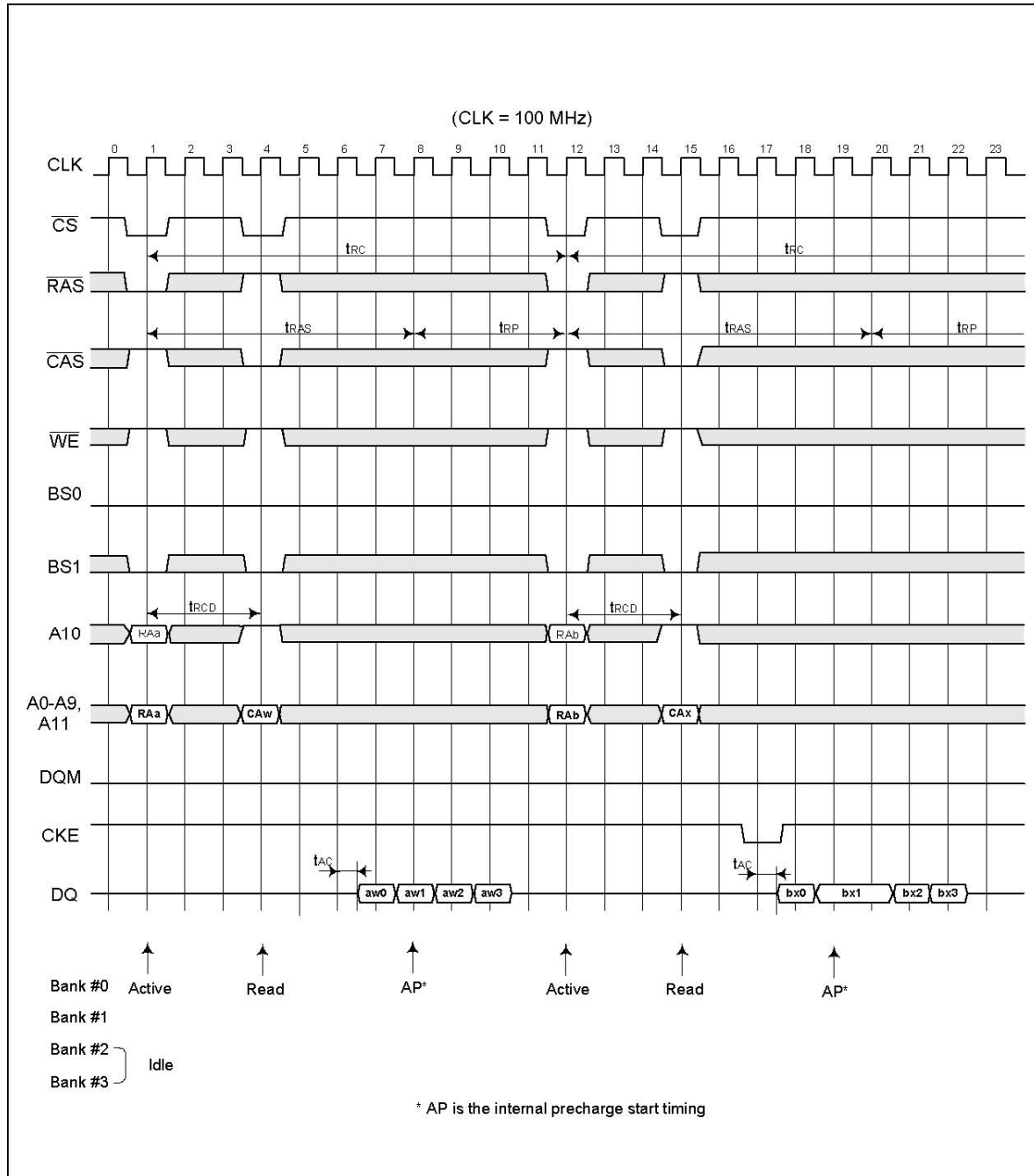
14.13 Page Mode Read/Write

(Burst Length = 8, CAS Latency = 3)



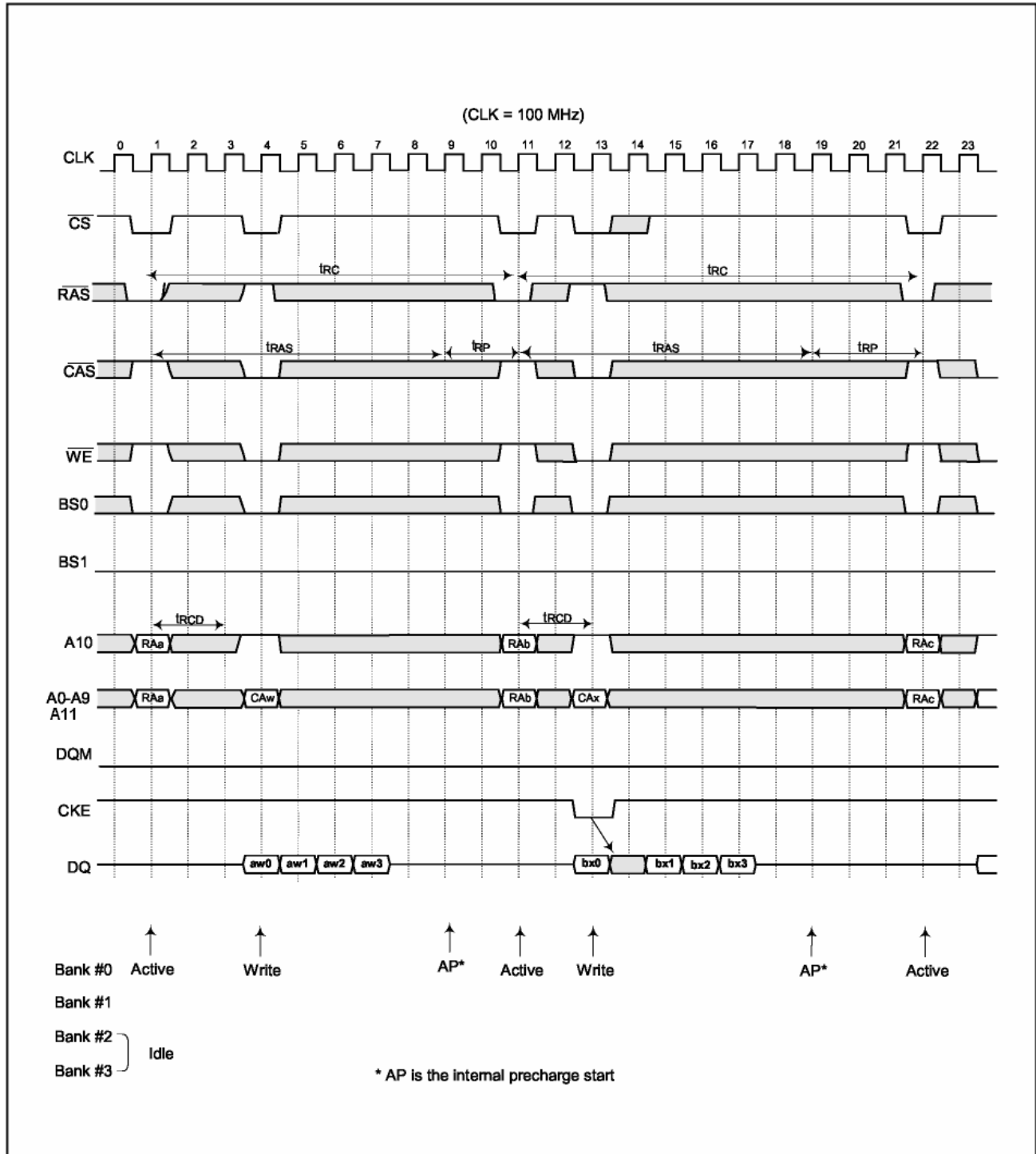
14.14 AutoPrecharge Read

(Burst Length = 4, CAS Latency = 3)

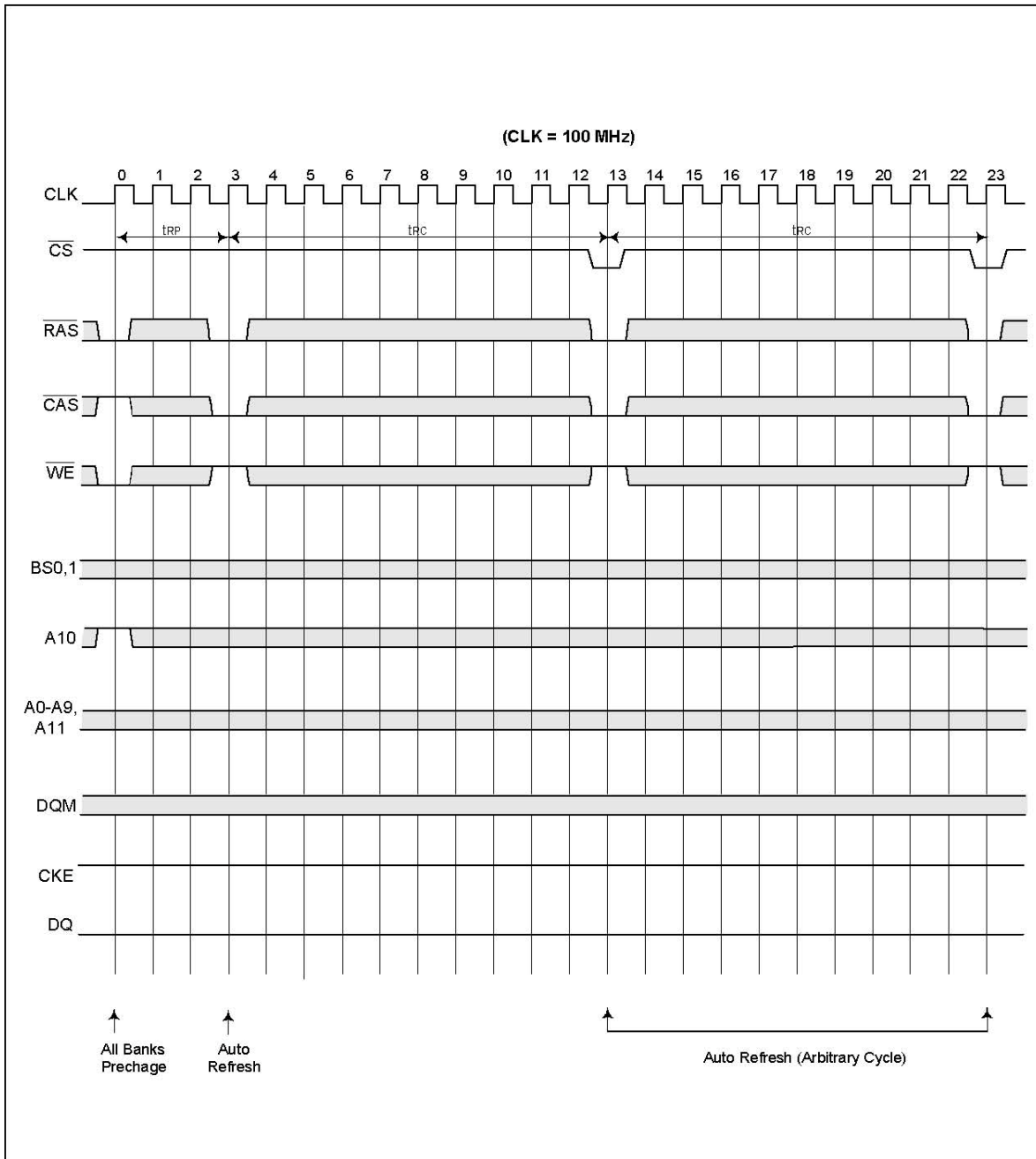


14.15 AutoPrecharge Write

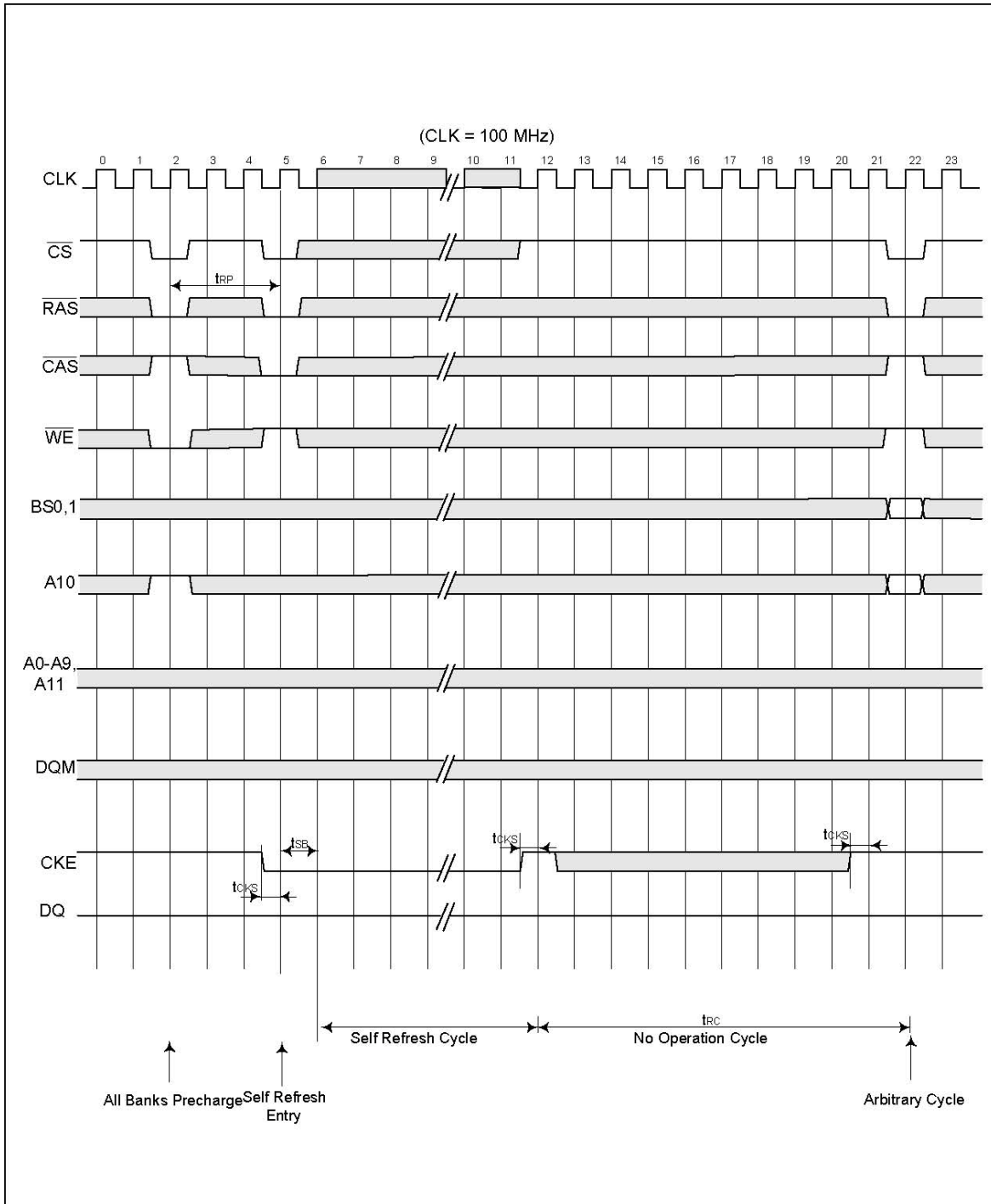
(Burst Length = 4)



14.16 AutoRefresh Cycle

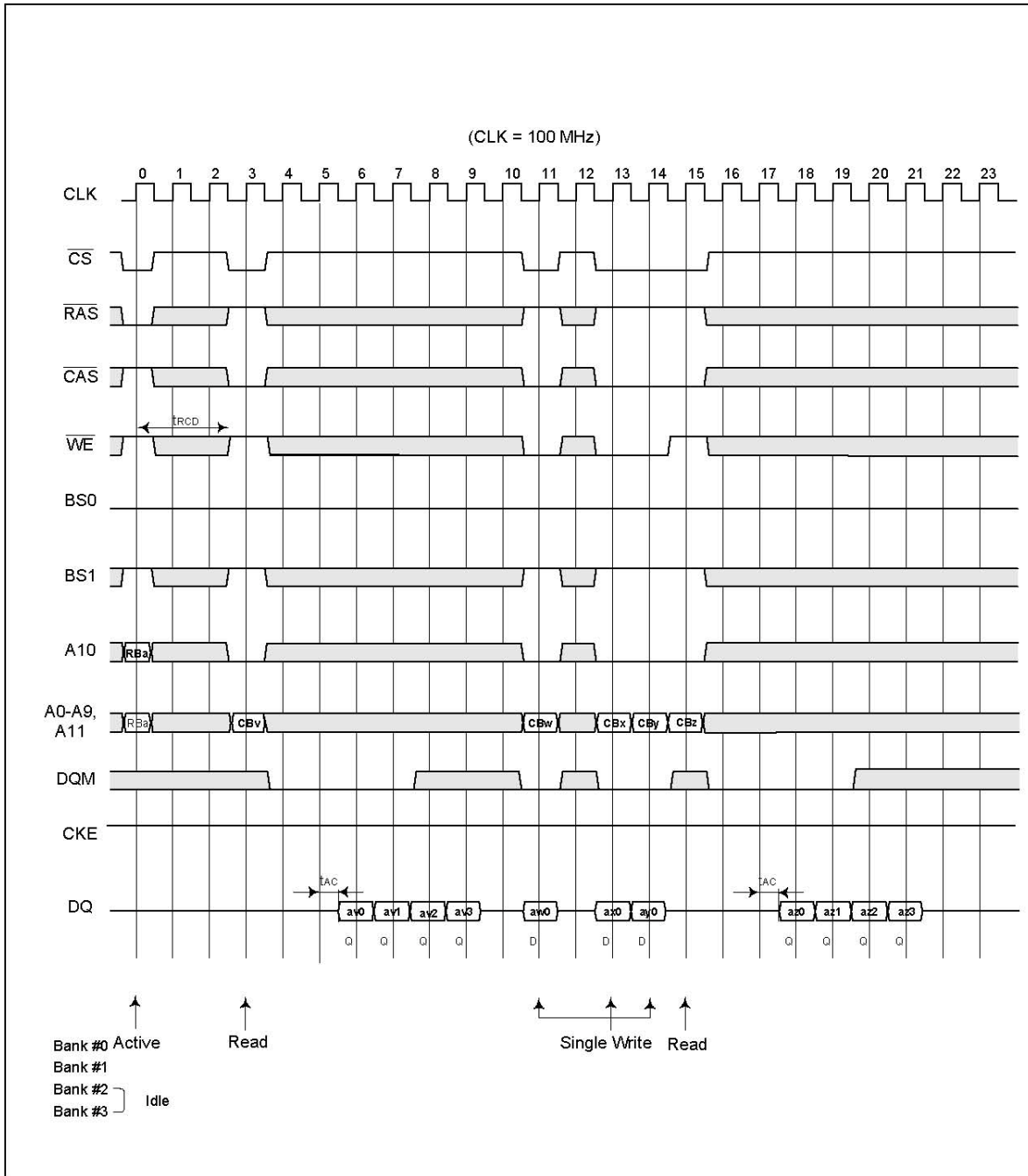


14.17 Self Refresh Cycle



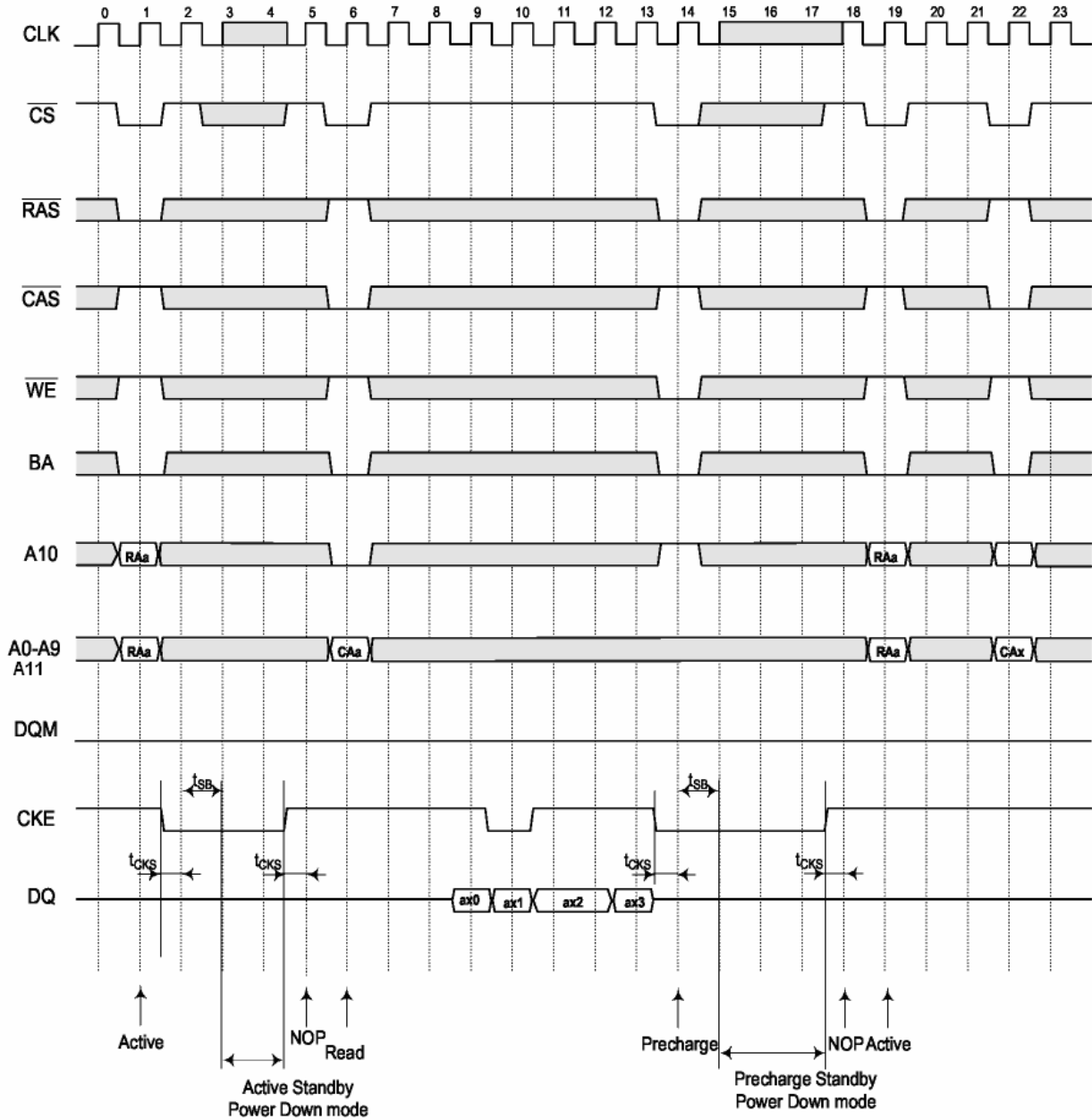
14.18 Bust Read and Single Write

(Burst Length = 4, CAS Latency = 3)



14.19 PowerDown Mode

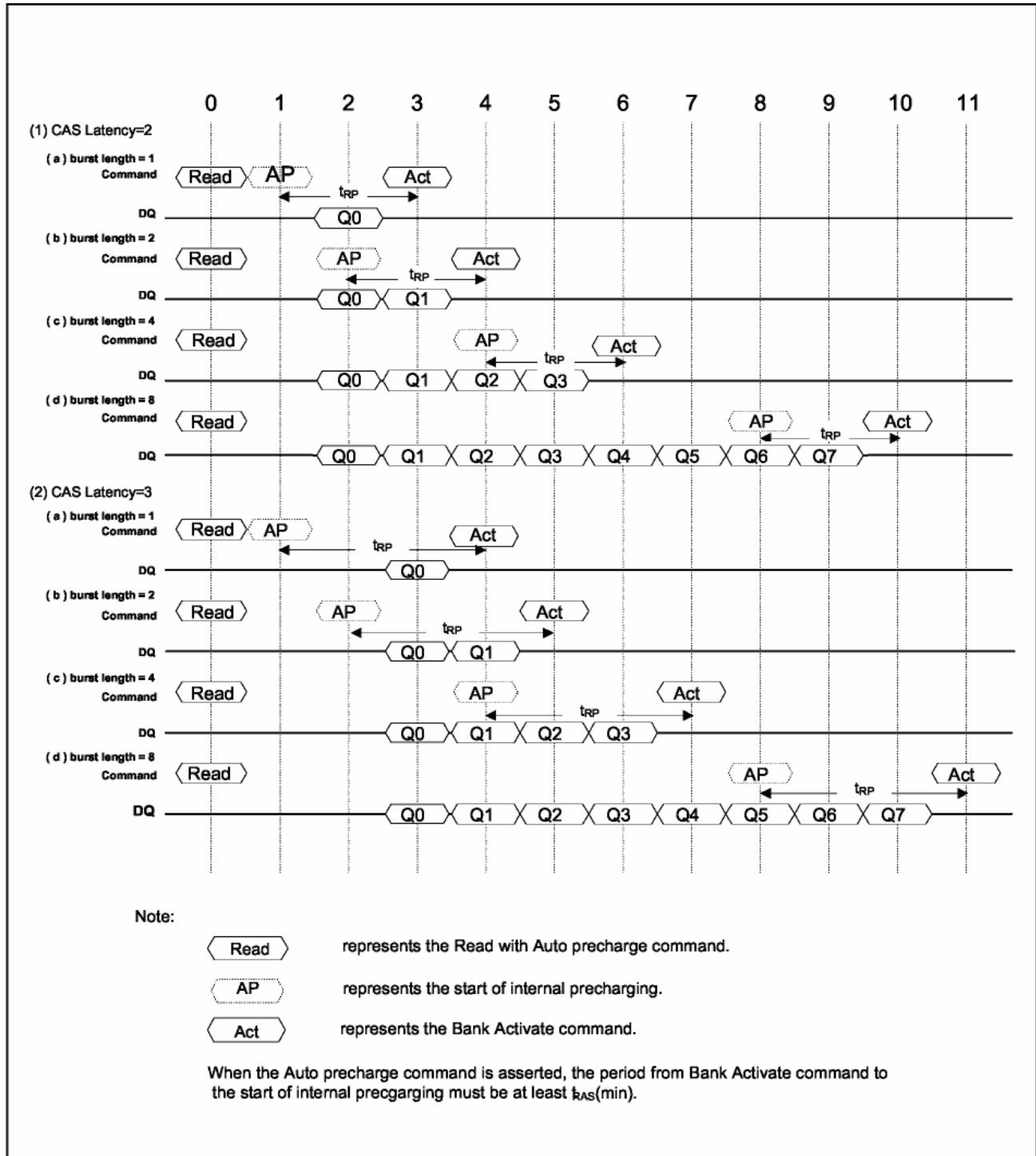
(CLK = 100 MHz)



Note: The PowerDown Mode is entered by asserting CKE "low".
 All Input/Output buffers (except CKE buffers) are turned off in the PowerDown mode.
 When CKE goes high, command input must be No operation at next CLK rising edge.

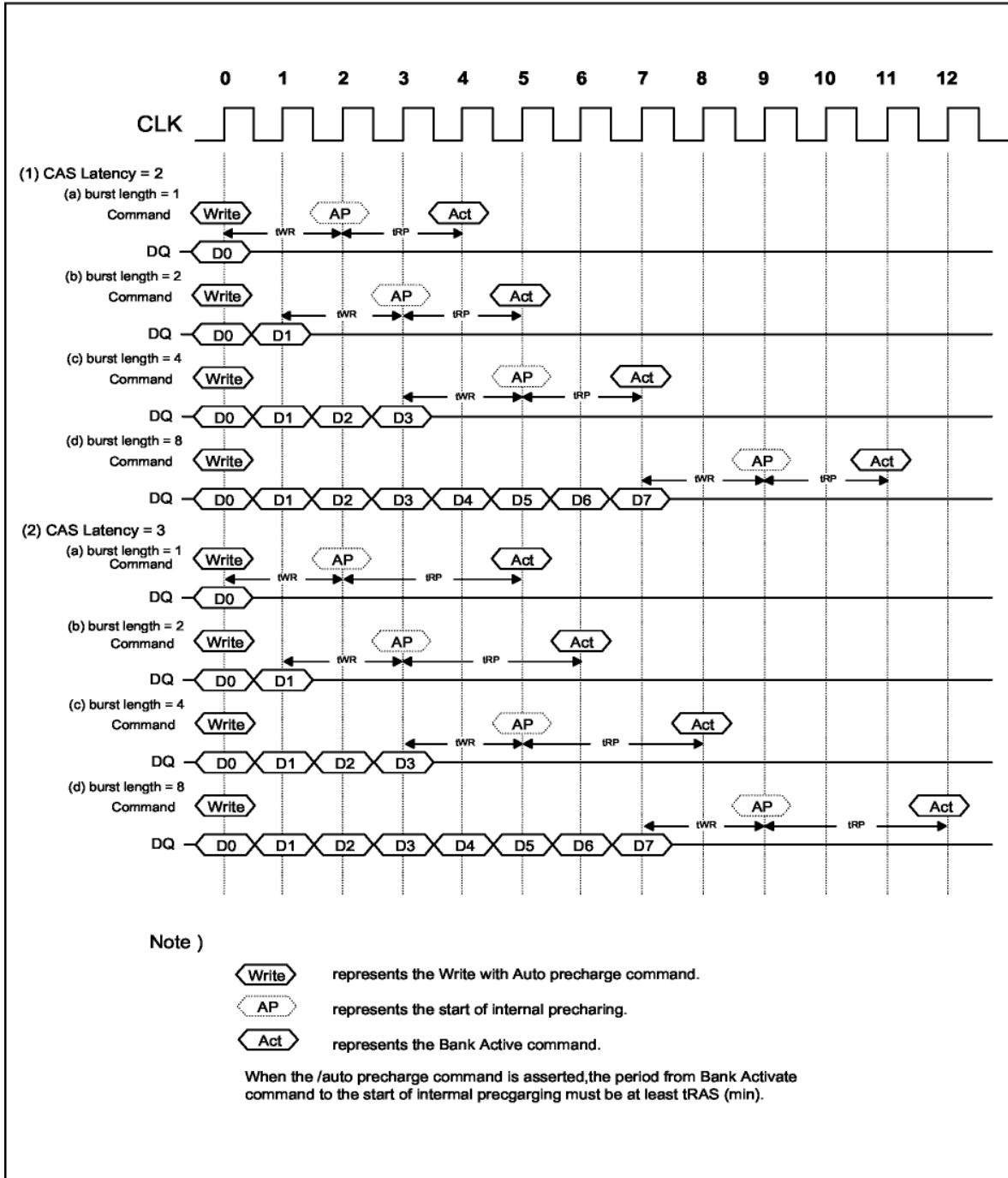
14.20 Autoprecharge Timing

(Read Cycle)



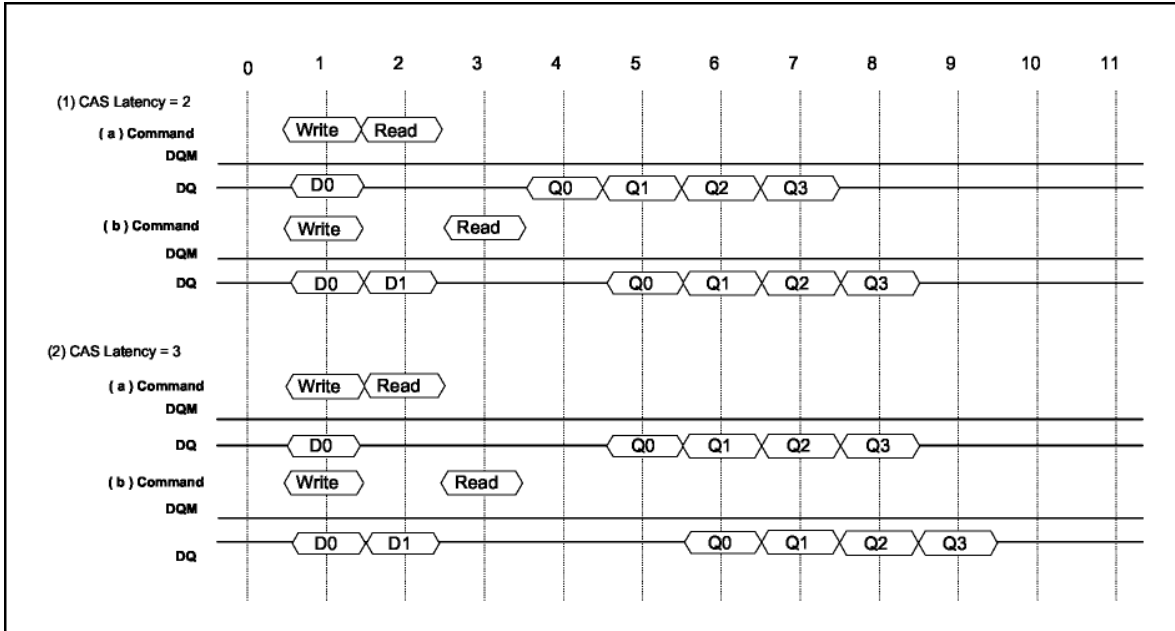
14.21 Autoprecharge Timing

(Write Cycle)



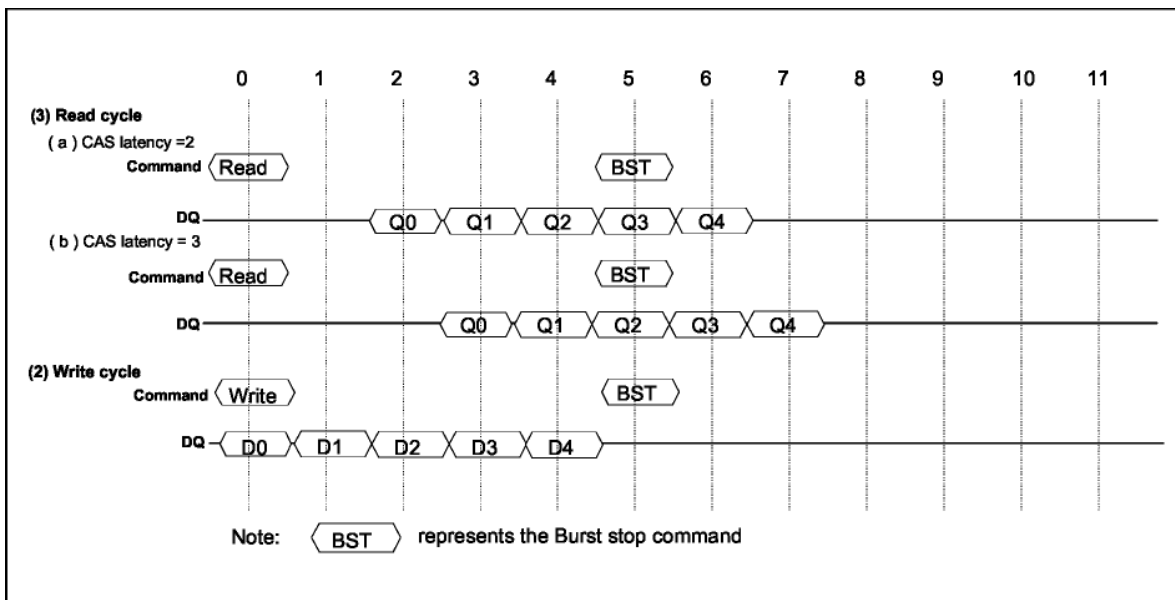
14.22 Timing Chart of Write-to-Read Cycle

In the case of Burst Length = 4



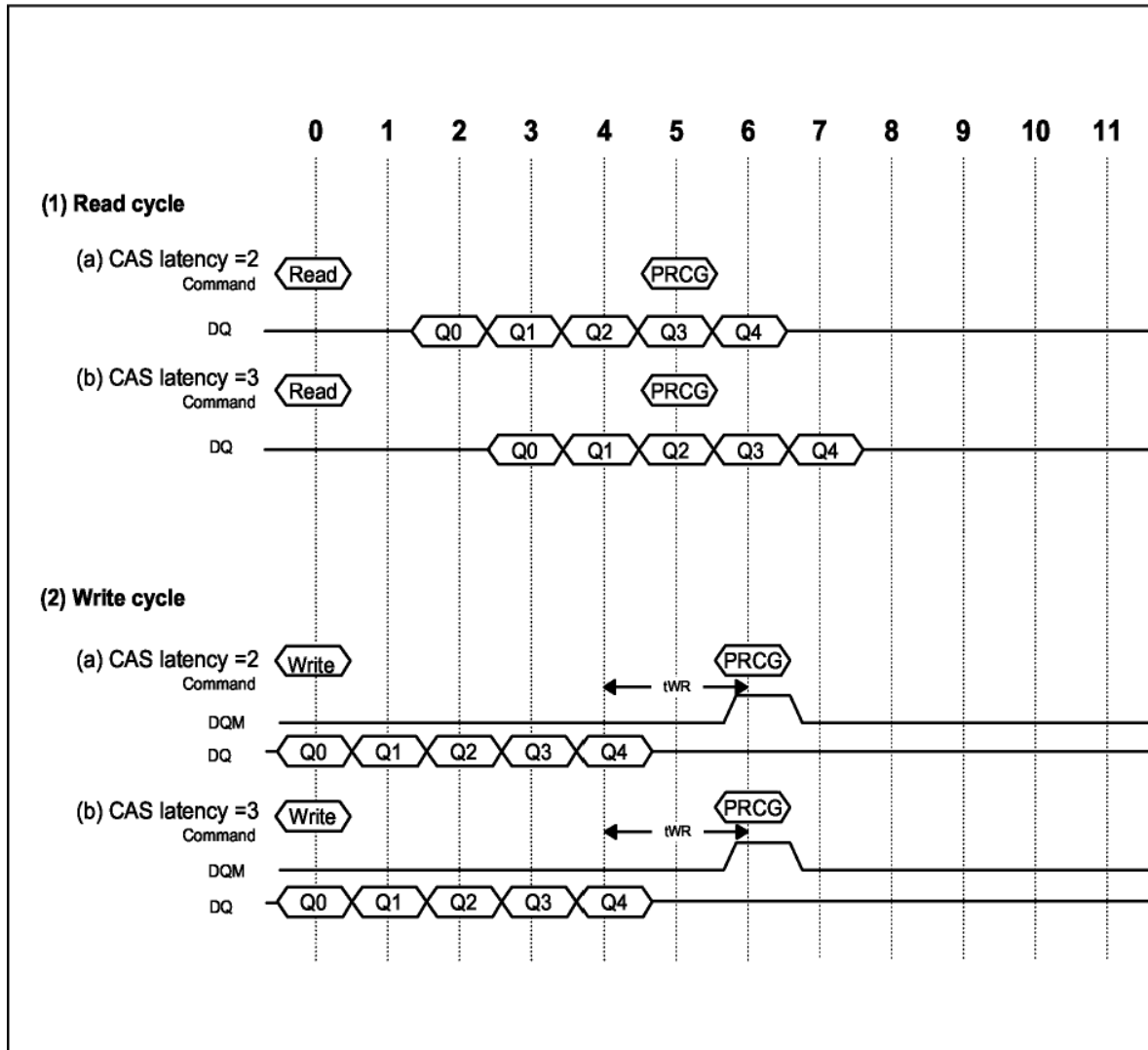
14.23 Timing Chart of Burst Stop Cycle

(Burst Stop Command)



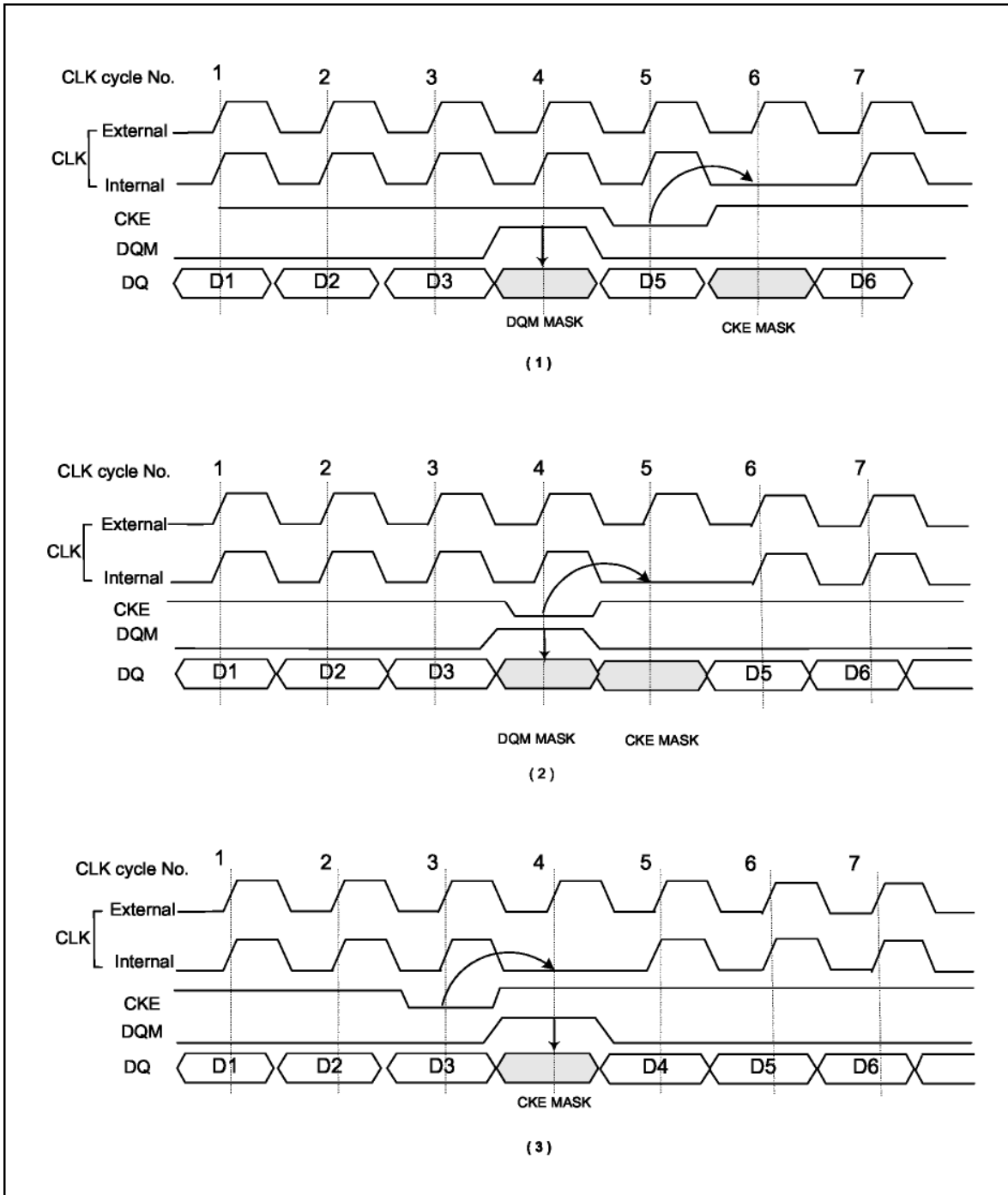
14.24 Timing Chart of Burst Stop Cycle

(Precharge Command)



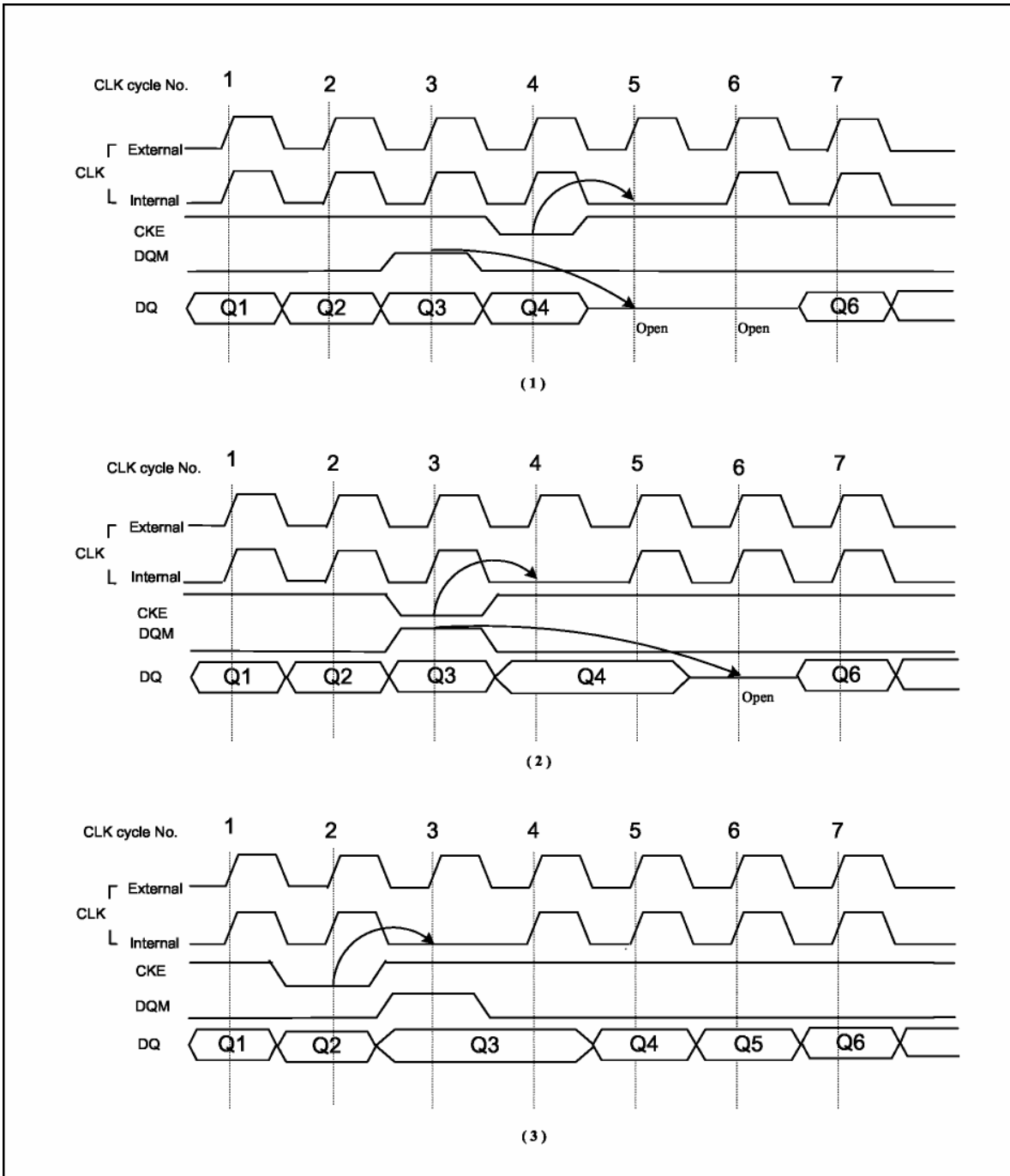
14.25 CKE/DQM Input Timing

(Write Cycle)

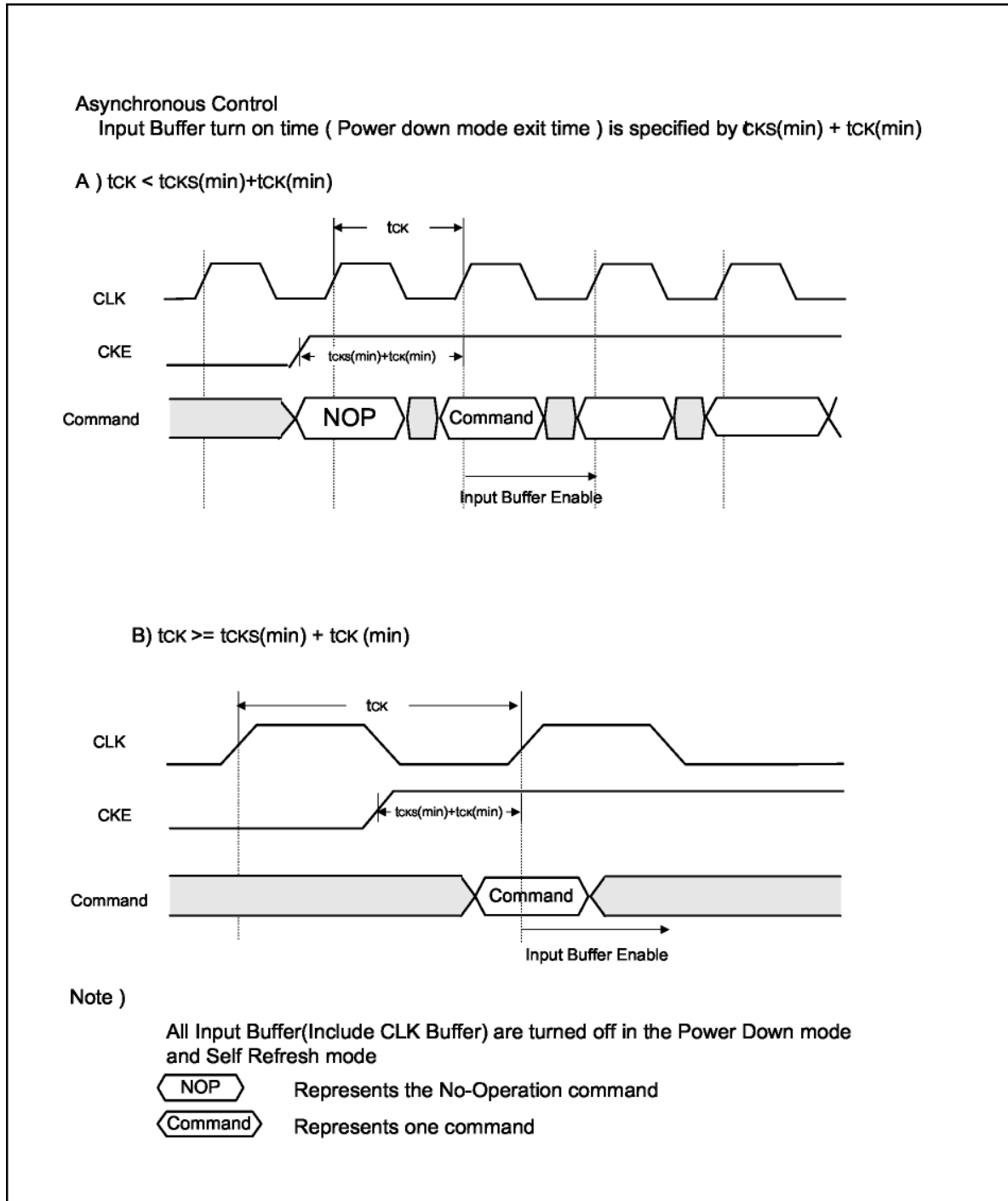


14.26CKE/DQM Input Timing

(Read Cycle)

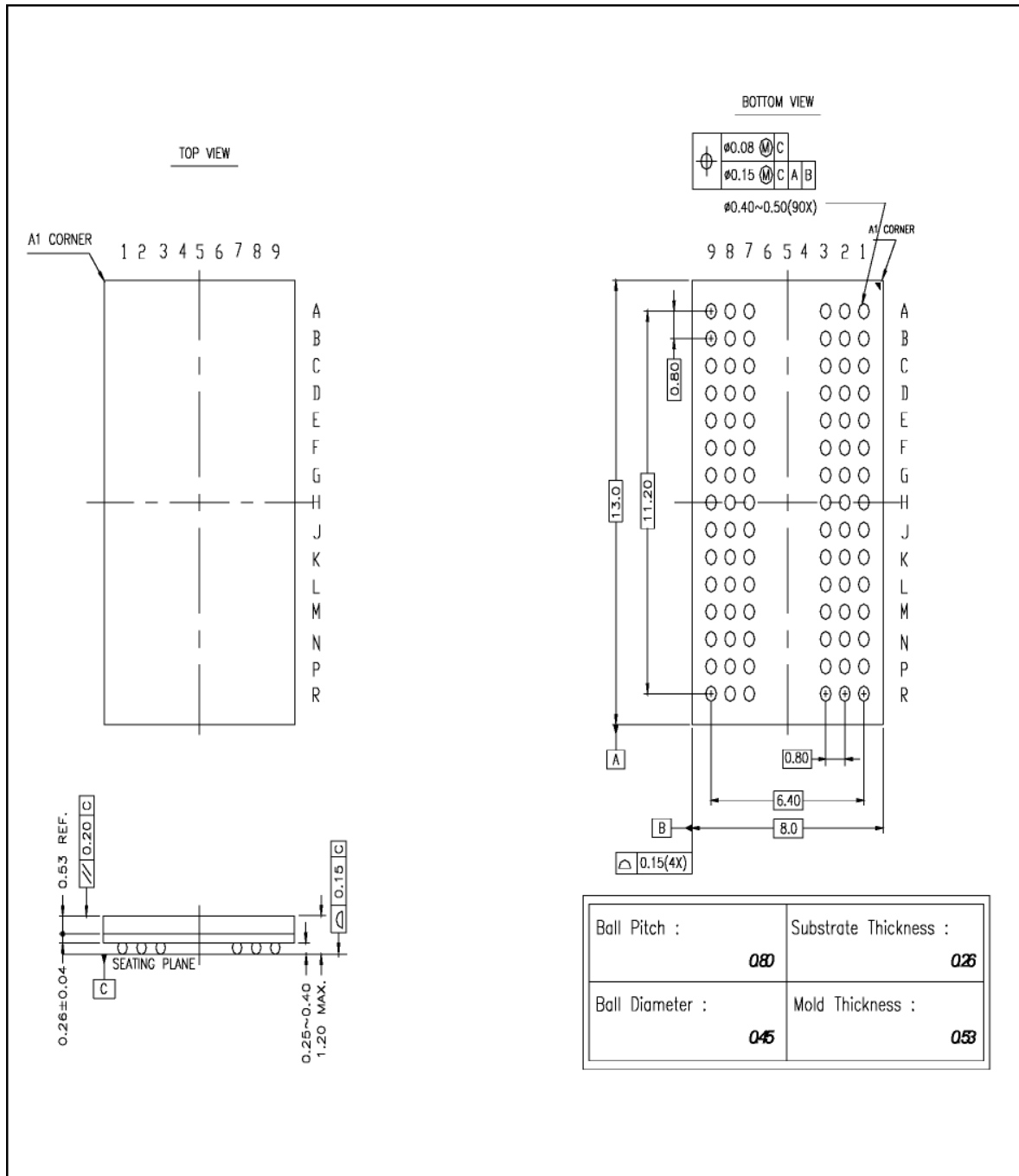


14.27 Self Refresh/Power Down Mode Exit Timing



15. PACKAGE DIMENSIONS

15.1 VFBGA 90 balls pitch=0.8mm



16. REVISION HISTORY

VERSION	DATE	PAGE	DESCRIPTION
A00	07/06/2005	—	Preliminary datasheet
A01	08/07/2006	—	Modified all parameter

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